



DACx0004 クワッド16/14/12ビット、1LSB INL、バッファ付き電圧出力 デジタル/アナログ・コンバータ

1 特長

- 真の16ビット性能: 1LSB INL/DNL (最大値)
- 超低グリッチ電力: 1nV-s
- 広い電源電圧範囲: 2.7V~5.5V
- レール・ツー・レール動作の出力バッファ
- 消費電流: 1mA/チャンネル
- 50MHzの4線式または3線式SPI準拠インターフェイス
- リードバックおよびデジタイズ・チェーン接続用SDOピン
- ゼロスケールまたはミッドスケールへのパワーオン・リセット
- 温度範囲: -40°C~+125°C
- 複数のパッケージ:
 - 小型の14ピンVSON
 - 14ピンTSSOP

2 アプリケーション

- 携帯機器
- PLCアナログ出力モジュール(4~20mA)
- 閉ループ・サーボ制御
- データ収集システム

3 概要

DAC80004/70004/60004 (DACx0004)は、高精度、低消費電力、電圧出力、クワッド・チャンネルの16/14/12ビット・デジタル/アナログ・コンバータ(DAC)です。DACx0004 デバイスは単調な特性を持ち、1LSB (最大値)を下回る優れた直線性を備えています。このDACのリファレンス入力、専用リファレンス・バッファにより内部でバッファされます。

DACx0004 デバイスは、内蔵のパワーオン・リセット回路により、PORピンの状態に応じてDAC出力をゼロスケールまたはミッドスケールで起動し、デバイスに有効なコードが書き込まれるまでその状態を保持します。消費電流が 1mA/チャンネルと非常に低いため、携帯型のバッテリー駆動機器に最適です。また、パワーダウン機能を備えており、消費電流を5Vで3μA (標準値)まで低減します。

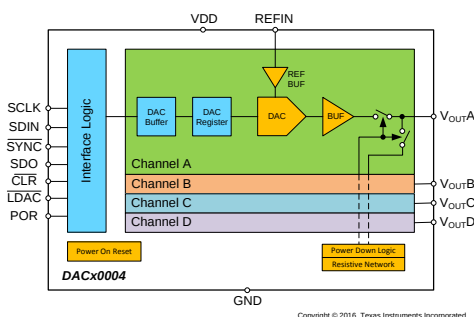
DACx0004 デバイスは、多用途の4線式または3線式シリアル・インターフェイスを使用し、最大50MHzのクロック速度で動作します。DACx0004 デバイスは、SDOピンも装備しているため、複数のデバイスをデジタイズ・チェーン接続できます。インターフェイスは、標準の SPI™、QSPI™、Microwire、およびデジタル信号プロセッサ(DSP)インターフェイスに準拠しています。DACx0004 デバイスは、組み立てやすい14ピンTSSOPパッケージまたは超小型の14ピンVSONパッケージで供給され、-40°C~125°Cの拡張工業用温度範囲で仕様が規定されています。

製品情報⁽¹⁾

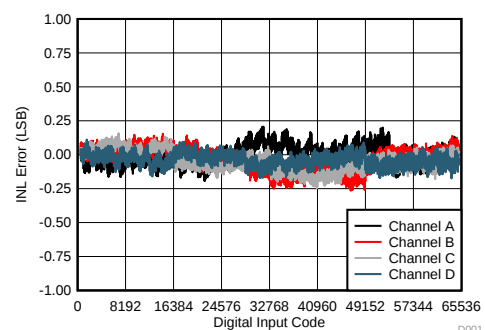
型番	パッケージ	本体サイズ(公称)
DACx0004	VSON (14)	3.00mm×4.00mm
DACx0004	TSSOP (14)	5.00mm×4.40mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

DACx0004のブロック図



直線性誤差とデジタル入力コードとの関係



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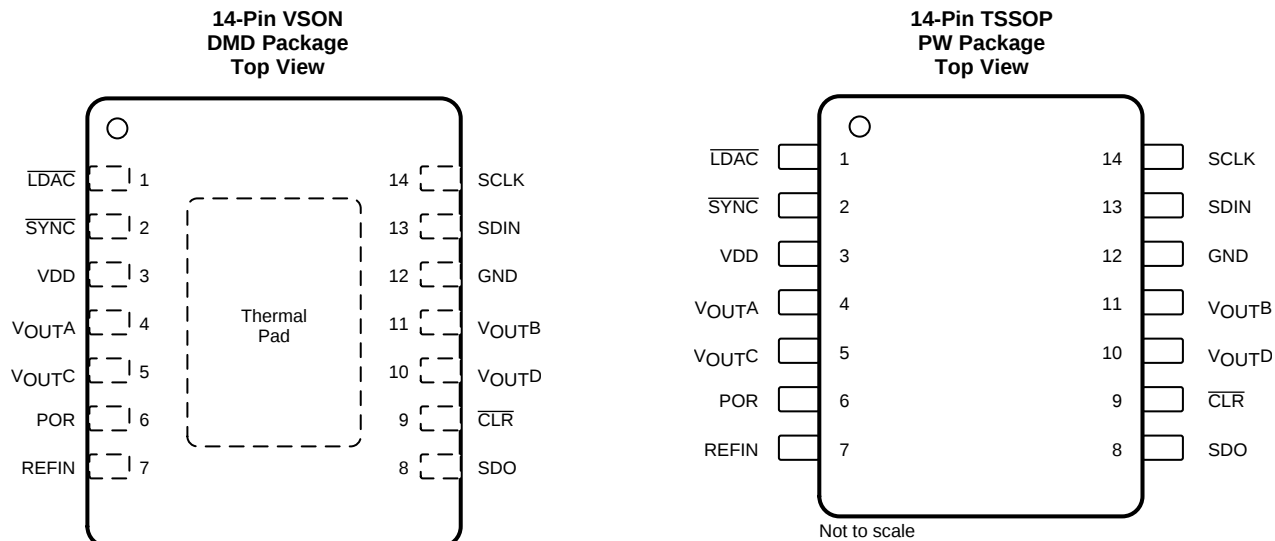
4 改訂履歴

Revision C (August 2016) から Revision D に変更	Page
• Changed 2.4 μ s From MAX to MIN value for t_{20} in the DACx0004 Timing Requirements table	8
• Changed From: t_{19} To: t_{20} in Figure 1	8
Revision B (June 2016) から Revision C に変更	Page
• Deleted thermal pad from PW-TSSOP pin configuration	3
Revision A (June 2016) から Revision B に変更	Page
• 追加「DAC80004IPWのデバイス・マーキング情報」を メカニカル、パッケージ、および注文情報 に	31
2016年4月発行のものから更新	Page
• 製品プレビューから量産データへ 変更	1

5 Device Comparison Table

DEVICE	RESOLUTION
DAC80004	16
DAC70004	14
DAC60004	12

6 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NUMBER		
$\overline{\text{CLR}}$	9	Digital Input	Clear DAC pin, falling edge sensitive
GND	12	Power	Ground
$\overline{\text{LDAC}}$	1	Digital Input	Load DAC pin, active low
POR	6	Digital Input	Power-on-reset configuration, Connecting the POR pin to GND powers up all four DACs to zero scale. Connecting this pin to VDD powers up all four DACs to midscale.
REFIN	7	Analog Input	Voltage reference input for all channels
SCLK	14	Digital Input	Serial interface shift clock
SDIN	13	Digital Input	Serial interface digital input
SDO	8	Digital Output	Serial interface digital output for readback and daisy chaining
$\overline{\text{SYNC}}$	2	Digital Input	Serial interface synchronization, active low
VDD	3	Power	Positive power supply (2.7 V to 5.5 V)
V _{OUTA}	4	Analog Output	DAC A output
V _{OUTB}	11	Analog Output	DAC B output
V _{OUTC}	5	Analog Output	DAC C output
V _{OUTD}	10	Analog Output	DAC D output

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

	MIN	MAX	UNIT
Voltage, VDD to GND	–0.3	7	V
Voltage, digital input or output to GND	–0.3	V _{DD} + 0.3	V
Voltage, analog input (REFIN) or output (V _{OUTX}) to GND	–0.3	V _{DD} + 0.3	V
Input current to any pin except supply pins	–10	10	mA
Maximum junction temperature		150	°C
Storage temperature range, T _{stg}	–60	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

		VALUE	UNIT
V _(ESD) Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±2000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
Voltage, VDD to GND	2.7		5.5	V
Voltage, analog input (REFIN) or output (V _{OUTX}) to GND	2.7 V ≤ V _{DD} ≤ 4.5 V	2.2	V _{DD} – 0.2	V
	4.5 V ≤ V _{DD} ≤ 5.5 V	2.2	V _{DD}	V
Ambient Operating Temperature, T _A	–40		125	°C

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		DACx0004		UNIT
		DMD (VSON)	PW (TSSOP)	
		14 PINS	14 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	39.6	99.1	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	27.3	23.4	°C/W
R _{θJB}	Junction-to-board thermal resistance	9.0	42.8	°C/W
ψ _{JT}	Junction-to-top characterization parameter	0.3	0.9	°C/W
ψ _{JB}	Junction-to-board characterization parameter	8.9	42.0	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	6.5	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Electrical Characteristics

All minimum/maximum specifications at $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.5\text{ V} \leq \text{REFIN}^{(1)} \leq V_{DD}$, $R_{\text{load}} = 5\text{ k}\Omega$ to GND, $C_{\text{load}} = 200\text{ pF}$ to GND (unless otherwise noted), Digital inputs held at 0 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC PERFORMANCE ⁽²⁾						
Resolution		DAC80004	16		Bits	
		DAC70004	14			
		DAC60004	12			
INL	Relative accuracy ⁽³⁾			±1	LSB	
DNL	Differential nonlinearity ⁽³⁾	Ensured monotonic		±1	LSB	
TUE	Total unadjusted error ⁽³⁾	T _A = +20°C to +40°C		1.5	mV	
		T _A = −40°C to +125°C		2		
ZCE	Zero code error	T _A = −40°C to +125°C, Code 0d into DAC		±0.2	±2	mV
		T _A = +25°C, Code 0d into DAC		±0.1		
ZCE-TC	Zero code error TC	T _A = −40°C to +125°C		±5	μV/°C	
OE	Offset error ⁽³⁾	T _A = +20°C to +40°C			±1.2	mV
		T _A = −40°C to +125°C		±0.2	±1.8	
		T _A = +25°C		±0.2		
OE-TC	Offset error drift	T _A = −40°C to +125°C		±4	μV/°C	
FSE	Full-scale error ⁽⁴⁾	T _A = +20°C to +40°C, Code 65535d into DAC			±0.05	%FSR
		T _A = −40°C to +125°C, Code 65535d into DAC		±0.01	±0.07	%FSR
		T _A = +25°C		±0.01		
FSE-TC	Full-scale error drift ⁽⁴⁾	T _A = −40°C to +125°C		±2	ppm FSR/°C	
GE	Gain error ⁽³⁾	T _A = −40°C to +125°C		±0.005	±0.05	%FSR
		T _A = +25°C		±0.005		
GE-TC	Gain drift	T _A = −40°C to +125°C		±2	ppm FSR/°C	
Output voltage drift vs.Time		T _A = +25°C, Vout = ¾ of full scale, 1900 hr		20	ppm FSR	
Load Regulation		T _A = +25°C, Vout =Mid Scale		0.003%		
PSRR	DC Power supply rejection ratio ⁽⁴⁾	T _A = +25°C, Vout = full scale		−92	dB	

(1) 200 mV headroom is required between REFIN and VDD when $2.7\text{ V} \leq V_{DD} \leq 4.5\text{ V}$.

(2) Output unloaded

(3) End point fit between codes Code 512 to Code 65,024 - DAC80004, Code 128 to Code 16,256 - DAC70004, Code 32 to Code 4064 - DAC60004, Output unloaded.

(4) With 100 mV headroom between DAC output and VDD.

Electrical Characteristics (continued)

All minimum/maximum specifications at $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.5\text{ V} \leq \text{REFIN}^{(1)} \leq V_{DD}$, $R_{load} = 5\text{ k}\Omega$ to GND, $C_{load} = 200\text{ pF}$ to GND (unless otherwise noted), Digital inputs held at 0 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DYNAMIC PERFORMANCE						
	Output voltage settling time	$\frac{1}{4}$ to $\frac{3}{4}$ scale and $\frac{3}{4}$ to $\frac{1}{4}$ scale settling to $\pm 1\text{ LSB}$, $R_L = 5\text{ k}\Omega$, $C_{load} = 200\text{ pF}$ to GND		5.8	8	μs
	Slew rate			1.5		$\text{V}/\mu\text{s}$
	Power-up time ⁽⁵⁾			100		μs
	Power-on glitch energy	Supply slew rate $< 5\text{ V}/\text{msec}$		8		mV
	Power-off glitch energy	DAC in power down mode ($1\text{ k}\Omega$ -GND), Supply slew rate $< 5\text{ V}/\text{msec}$		7		mV
	Output noise	0.1 Hz to 10 Hz		5		μV_{pp}
		100 kHz BW		100		μV_{RMS}
	Output noise density	Measured at 1 kHz		60		$\text{nV}/\sqrt{\text{Hz}}$
		Measured at 10 kHz		55		
THD	Total harmonic distortion	$\text{REFIN} = 3\text{ V} \pm 0.2\text{ V}_{pp}$, Frequency = 10 kHz, DAC at mid scale, specified by design		-80		dB
PSRR	AC power supply rejection ratio	200 mV 50 Hz and 60 Hz sine wave superimposed on power supply voltage (AC analysis)		-90		dB
	Code change glitch impulse	1 LSB change around major carry, Software LDAC mode		1		nV-s
	Channel-to-channel AC (analog) crosstalk	Full-scale swing on adjacent channel, Hardware LDAC mode		1		nV-s
	Channel-to-channel DC crosstalk	Full-scale swing on adjacent channels, Measured channel at zero scale		1		LSB
		Full-scale swing on all channel, Measured channel at zero scale		1		
	Digital crosstalk	DAC code mid scale, Adjacent input buffer change from 0000h to FFFFh or vice versa		0.2		nV-S
	Reference feedthrough	$\text{REFIN} = 3\text{ V} \pm 0.86\text{ V}_{pp}$, Frequency = 100 Hz to 100 kHz, DAC at zero scale		-85		dB
	Digital feedthrough	At SCLK = 1 MHz, DAC output static at mid scale		0.2		nV-s
OUTPUT CHARACTERISTICS						
	Voltage range		0		V_{DD}	V
	Headroom	Output loaded $5\text{ k}\Omega$, DAC code FFFFh		0.1		V
		Output loaded $0.5\text{ k}\Omega$, DAC code FFFFh		10		%FSR
RL	Resistive load		0.5			$\text{k}\Omega$
CL	Capacitive load	$R_L = \infty$		1		nF
		$R_L = 5\text{ k}\Omega$		2		
RO	DC output impedance	Normal mode		0.5		Ω
		Power down with $100\text{ k}\Omega$ network		100		$\text{k}\Omega$
		Power down with $1\text{ k}\Omega$ network		1		$\text{k}\Omega$
	Short circuit current			36		mA

(5) Time to exit power-down mode into normal mode. Measured from 32nd falling edge SCLK to 90% of DAC final value, Characterized at mid scale.

Electrical Characteristics (continued)

All minimum/maximum specifications at $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.5\text{ V} \leq \text{REFIN}^{(1)} \leq V_{DD}$, $R_{\text{load}} = 5\text{ k}\Omega$ to GND, $C_{\text{load}} = 200\text{ pF}$ to GND (unless otherwise noted), Digital inputs held at 0 V

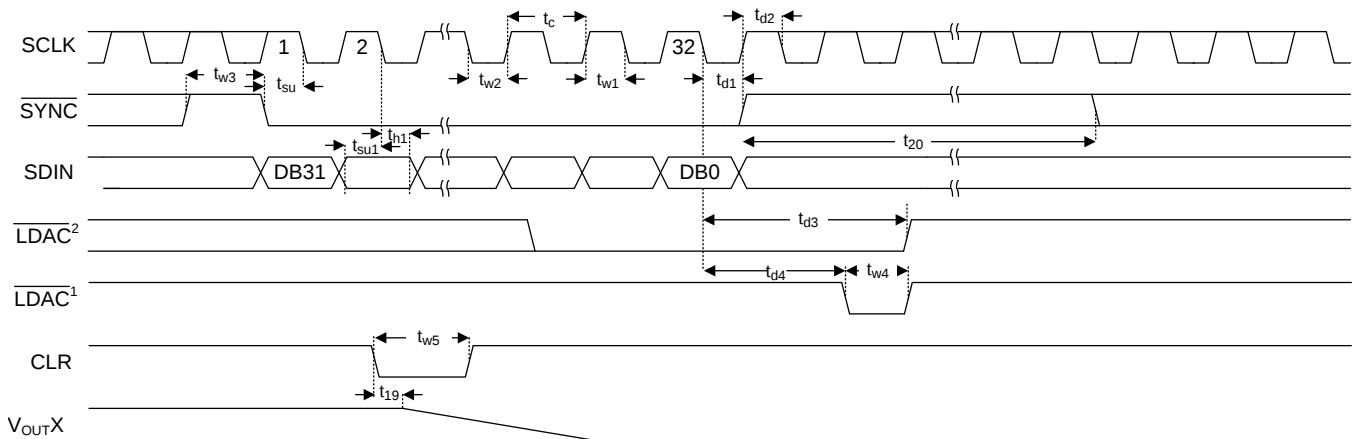
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
VOLTAGE REFERENCE INPUT						
Reference input range		$2.7\text{ V} \leq V_{DD} \leq 4.5\text{ V}$	2.2	$V_{DD} - 0.2$		V
		$4.5\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.2	V_{DD}		
Reference input current					450	μA
Reference input impedance				15		$\text{k}\Omega$
Reference input capacitance				10		pF
MBW	Multiplying bandwidth			340		kHz
DIGITAL INPUTS						
V_{IH}	High-level input voltage		2.3			V
V_{IL}	Low-level input voltage				0.7	V
Input leakage		$0 < V_{\text{DIGITAL INPUT}} < V_{DD}$			± 1	μA
Pin capacitance				4		pF
DIGITAL OUTPUTS						
V_{OH}	High-level output voltage	$I_{OH} = 2\text{ mA}$	$V_{DD} - 1$			V
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{ mA}$			0.7	V
Pin capacitance				7		pF
POWER SUPPLY REQUIREMENTS						
V_{DD}	Supply voltage		2.7		5.5	V
I_{VDD}	Supply current	$T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, Normal mode		4	5.5	mA
		$T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, Power-down mode		3	7	μA
	Power dissipation	$T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, Normal mode		20		mW
TEMPERATURE RANGE						
T_A	Specified performance		-40		125	$^{\circ}\text{C}$

7.6 DACx0004 Timing Requirements

At $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $T_{\text{rise}} = T_{\text{fall}} = 1 \text{ nV/sec}$ (10% to 90% of V_{DD}) and timed from a voltage level of $(V_{IL} + V_{IH})/2$, SDO pin loaded with 10 pF

		4.5 V ≤ V _{DD} ≤ 5.5 V			2.7 V ≤ V _{DD} ≤ 4.5 V			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
SERIAL WRITE and READ								
t _c	SCLK cycle time	20			40			ns
t _{w1}	SCLK high pulse duration	10			20			ns
t _{w2}	SCLK low pulse duration	10			20			ns
t _{su}	$\overline{\text{SYNC}}$ to SCLK falling edge setup time	15			30			ns
t _{su1}	Data setup time	5			10			ns
t _{h1}	Data hold time	5			10			ns
t _{d1}	SCLK falling edge to $\overline{\text{SYNC}}$ rising edge delay time	5			10			ns
t _{w3}	Minimum $\overline{\text{SYNC}}$ high pulse duration ⁽¹⁾	25			35			ns
t _{d2}	$\overline{\text{SYNC}}$ rising edge to SCLK fall ignore delay time	15			20			ns
t _{w4}	$\overline{\text{LDAC}}$ pulse duration low	20			30			ns
t _{d3}	SCLK falling edge to $\overline{\text{LDAC}}$ rising edge delay time	10			20			ns
t _{w5}	$\overline{\text{CLR}}$ minimum pulse duration low	10			20			ns
t _{d4}	SCLK falling edge to $\overline{\text{LDAC}}$ falling edge delay time	10			20			ns
t _v	SCLK rising edge to SDO valid time	18			18			ns
t _{d5}	SCLK falling edge to $\overline{\text{SYNC}}$ rising edge delay time	5			10			ns
t _{d6}	$\overline{\text{SYNC}}$ rising edge to SCLK rising edge delay time	5			10			ns
t _{d7}	$\overline{\text{SYNC}}$ rising edge to $\overline{\text{LDAC}}$ or $\overline{\text{CLR}}$ falling edge delay time	20			40			ns
t ₁₉	$\overline{\text{CLR}}$ pulse activation time	20			20			ns
t ₂₀	Successive DAC Update	2.4			2.4			μs

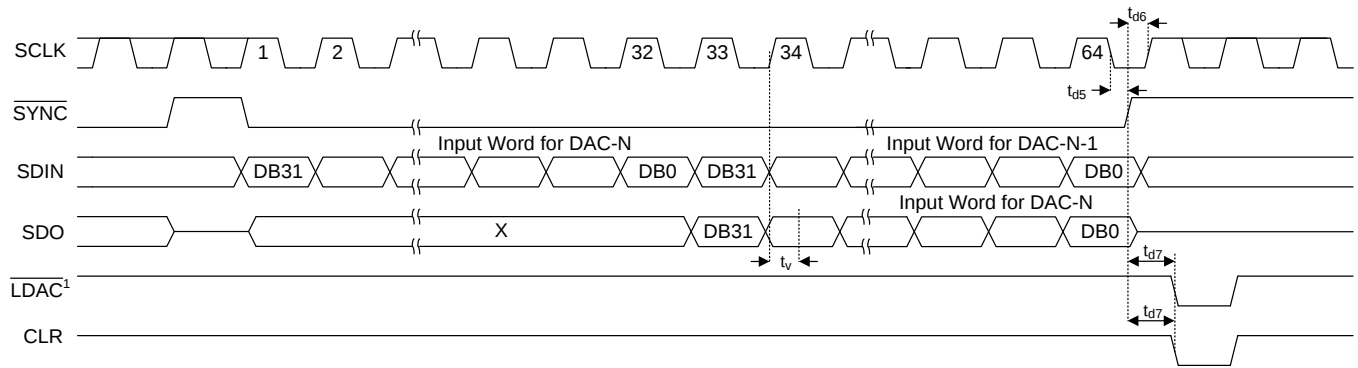
(1) Does not include output settling time



(1) Asynchronous $\overline{\text{LDAC}}$ update

(2) Synchronous $\overline{\text{LDAC}}$ update

Figure 1. Stand-Alone Timing



(1) Asynchronous $\overline{\text{LDAC}}$ update

Figure 2. Daisy-Chain Timing

7.7 Typical Characteristics

At $T_A = 25^\circ\text{C}$, $V_{DD} = 5.5\text{ V}$, $\text{REFIN} = 5.45\text{ V}$, DAC outputs unloaded, unless otherwise noted.

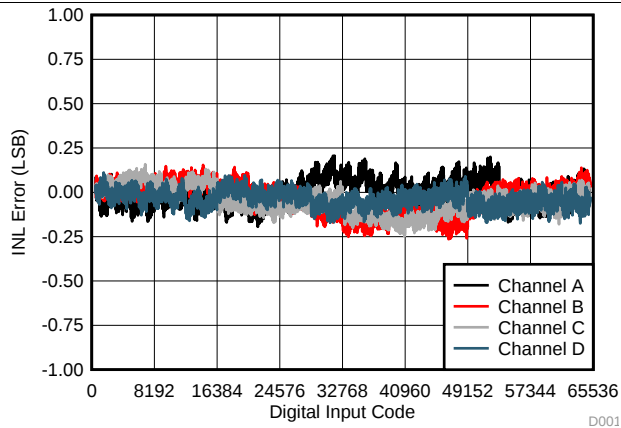


Figure 3. Linearity Error vs Digital Input Code

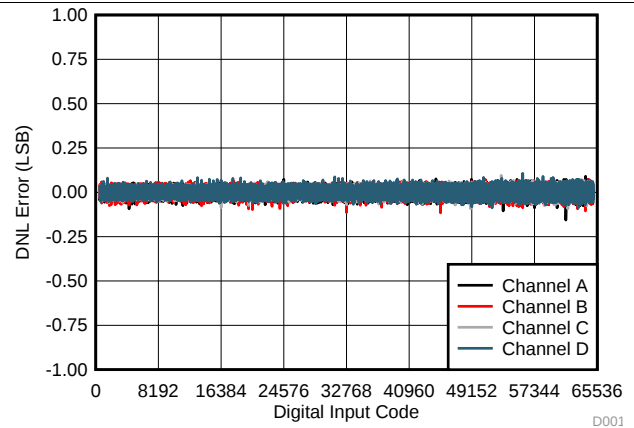
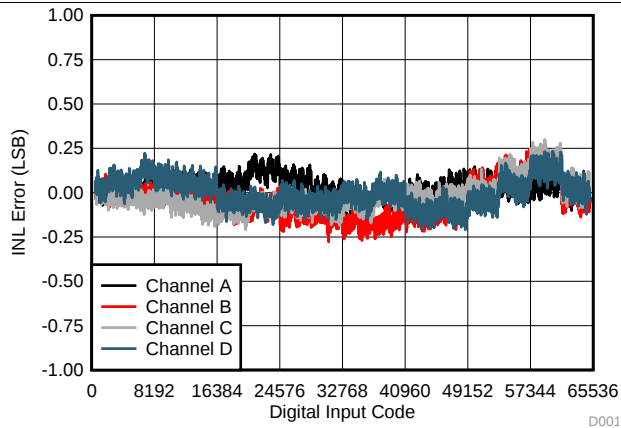
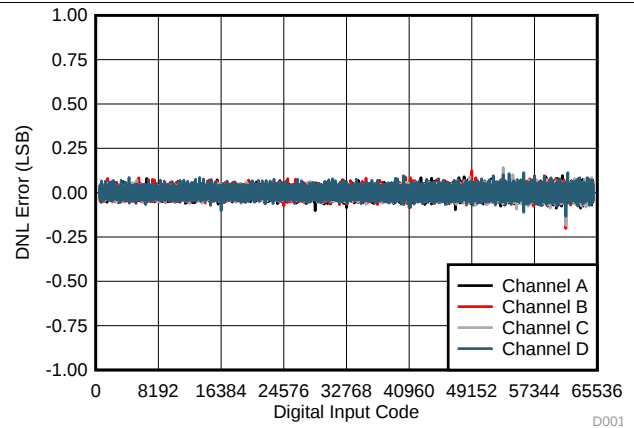


Figure 4. Differential Linearity Error vs Digital Input Code



DAC load 5 kΩ/200 pF

Figure 5. Linearity Error vs Digital Input Code



DAC load 5 kΩ/200 pF

Figure 6. Differential Linearity Error vs Digital Input Code

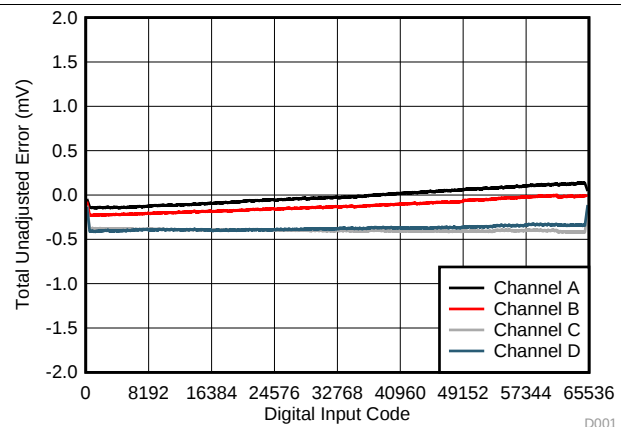
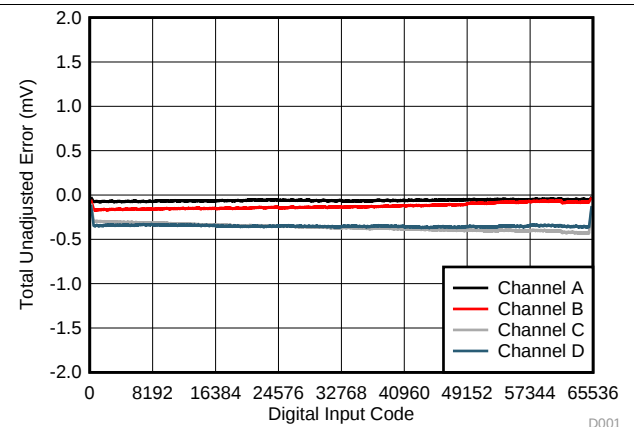


Figure 7. Total Unadjusted Error vs Digital Input Code



DAC load 5 kΩ/200 pF

Figure 8. Total Unadjusted Error vs Digital Input Code

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_{DD} = 5.5\text{ V}$, $\text{REFIN} = 5.45\text{ V}$, DAC outputs unloaded, unless otherwise noted.

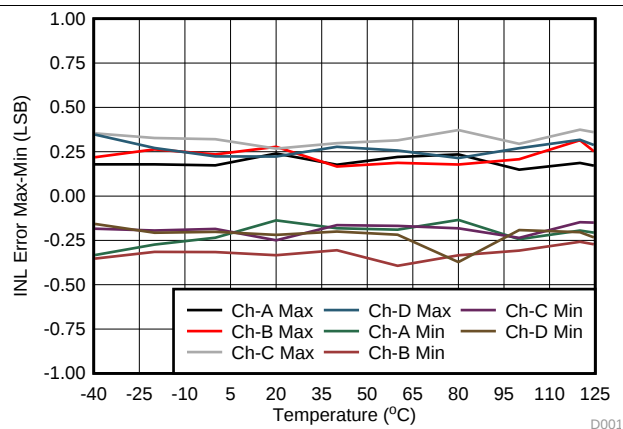


Figure 9. Linearity Error (Max-Min) vs Temperature

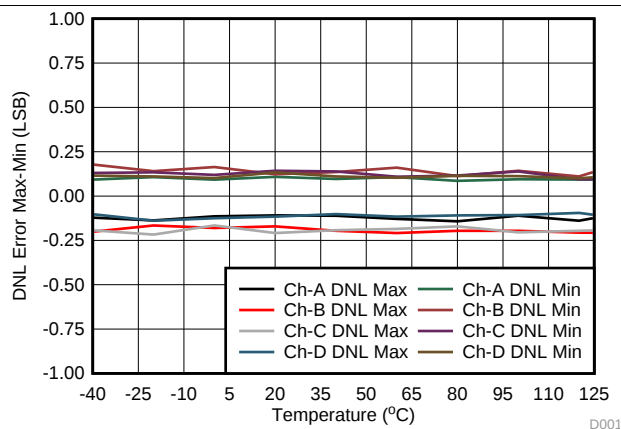


Figure 10. Differential Linearity Error (Max-Min) vs Temperature

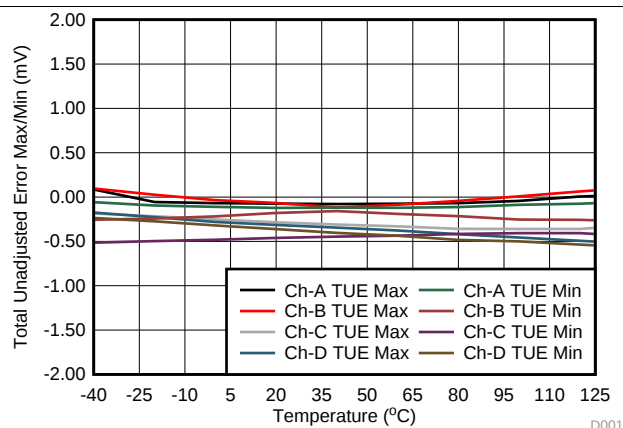


Figure 11. Total Unadjusted Error Max/Min vs Temperature

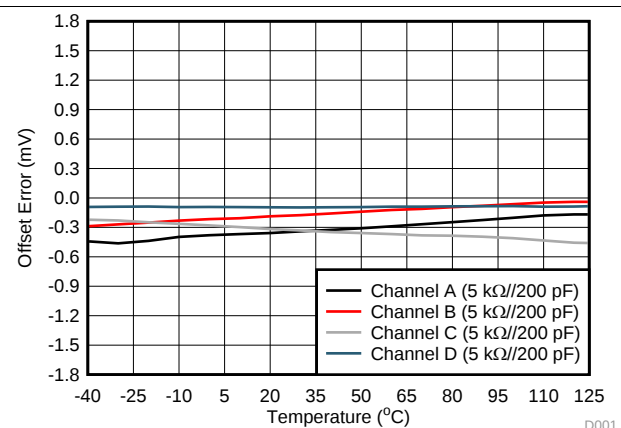


Figure 12. Offset Error vs Temperature

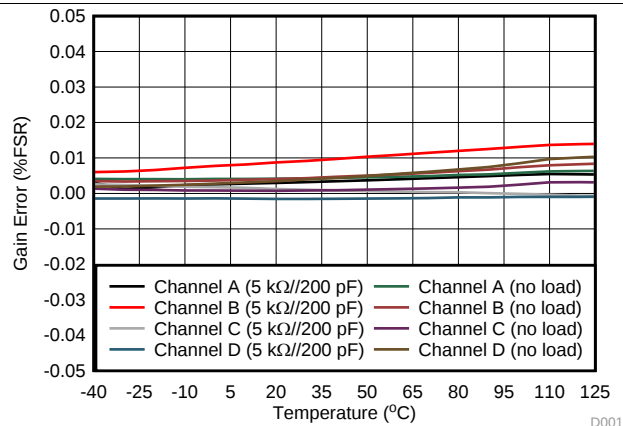


Figure 13. Gain Error vs Temperature

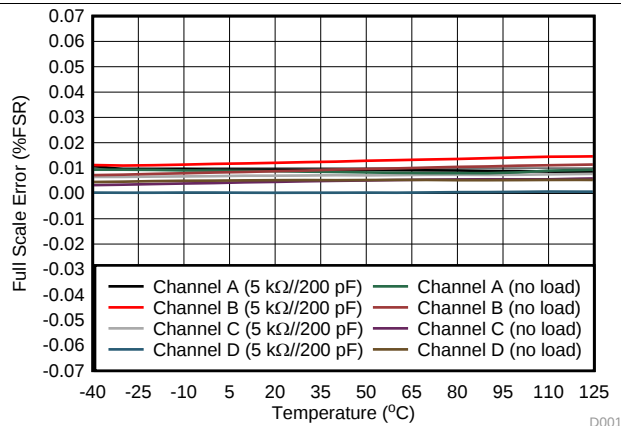


Figure 14. Full Scale Error vs Temperature

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_{DD} = 2.7\text{ V}$, $\text{REFIN} = 2.5\text{ V}$, DAC outputs unloaded, unless otherwise noted.

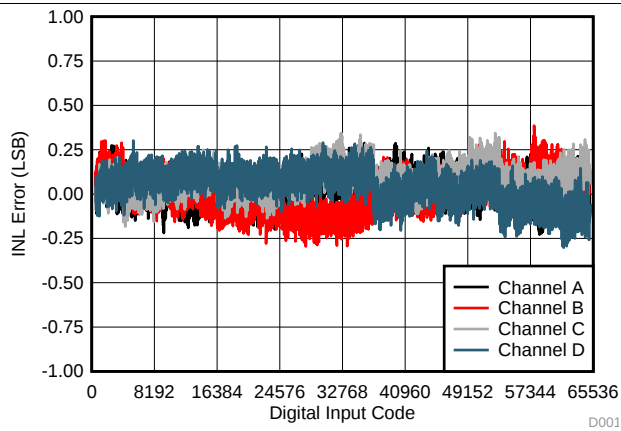


Figure 15. Linearity Error vs Digital Input Code

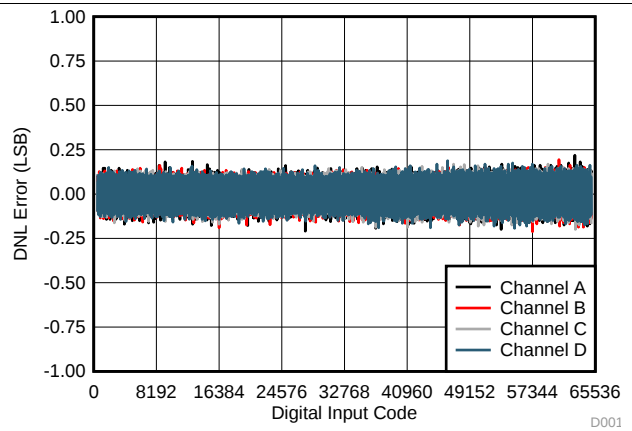
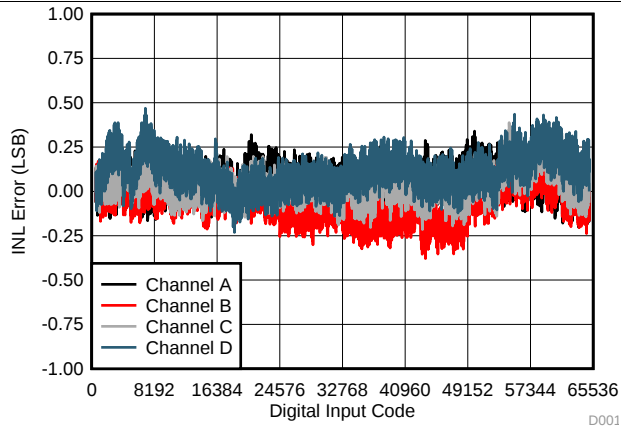
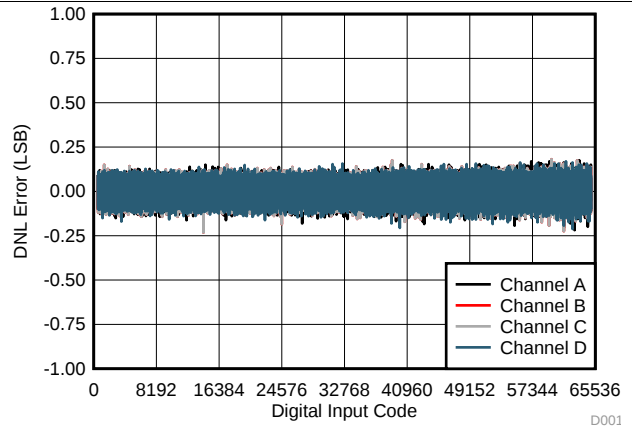


Figure 16. Differential Linearity Error vs Digital Input Code



DAC load 5 kΩ//200 pF

Figure 17. Linearity Error vs Digital Input Code



DAC load 5 kΩ//200 pF

Figure 18. Differential Linearity Error vs Digital Input Code

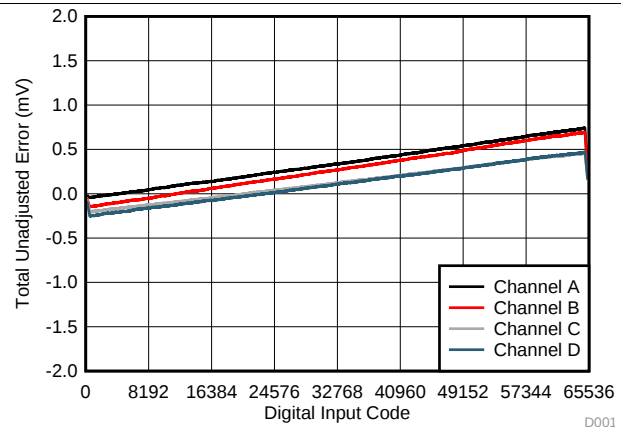
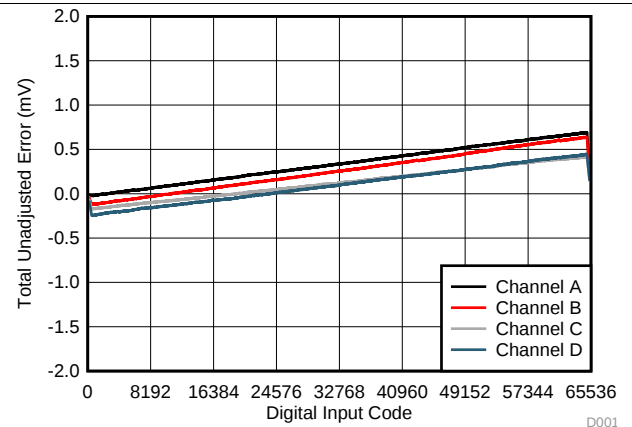


Figure 19. Total Unadjusted Error vs Digital Input Code



DAC load 5 kΩ//200 pF

Figure 20. Total Unadjusted Error vs Digital Input Code

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_{DD} = 2.7\text{ V}$, $\text{REFIN} = 2.5\text{ V}$, DAC output unloaded, unless otherwise noted.

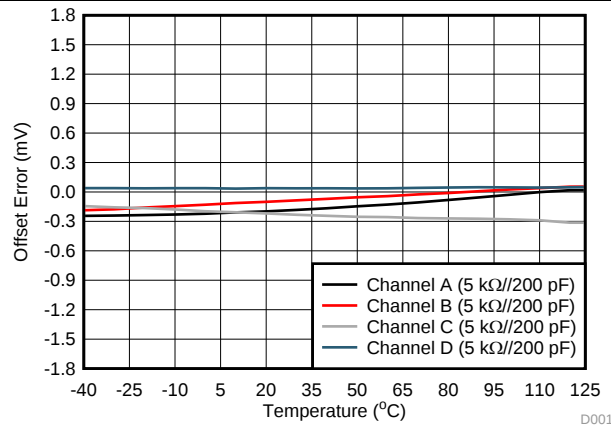


Figure 21. Offset Error vs Temperature

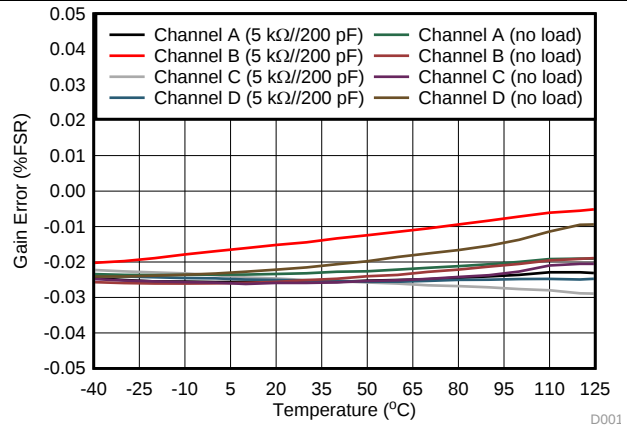


Figure 22. Gain Error vs Temperature

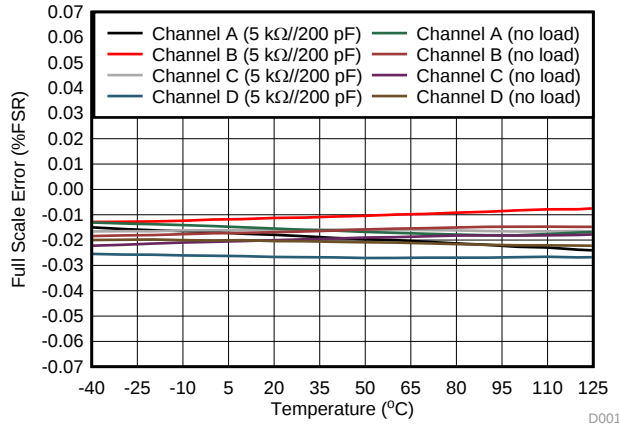
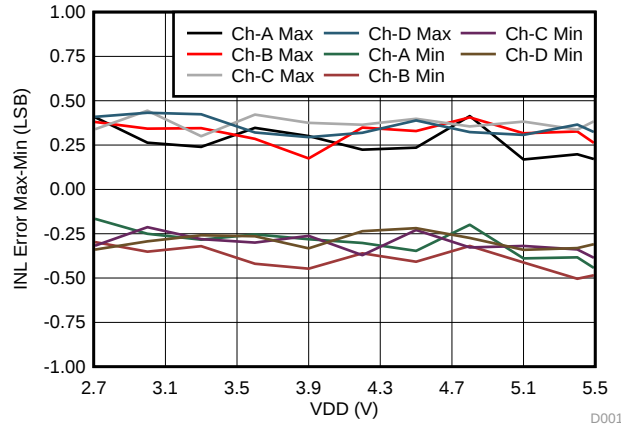
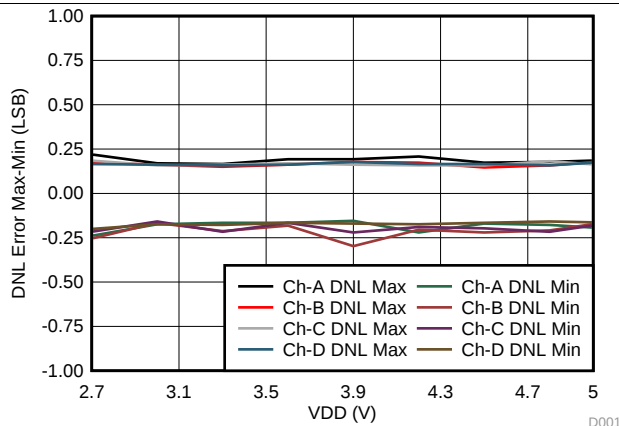


Figure 23. Full Scale Error vs Temperature



DAC load 5 kΩ/200 pF

Figure 24. Linearity Error (Max-Min) vs Power Supply Voltage



DAC load 5 kΩ/200 pF

Figure 25. Differential Linearity Error (Max-Min) vs Power Supply Voltage

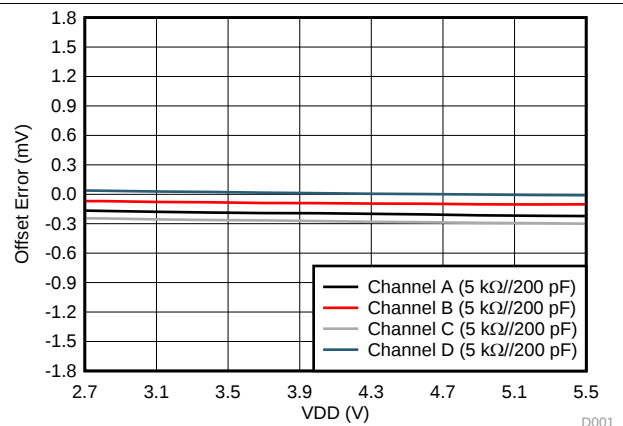


Figure 26. Offset Error vs Power Supply Voltage

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_{DD} = 5.5\text{ V}$, $\text{REFIN} = 2.5\text{ V}$, DAC output load = $5\text{ k}\Omega \parallel 200\text{ pF}$, unless otherwise noted.

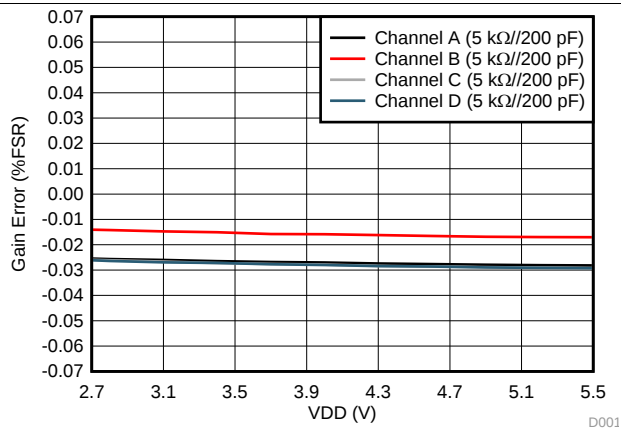


Figure 27. Gain Error vs Power Supply Voltage

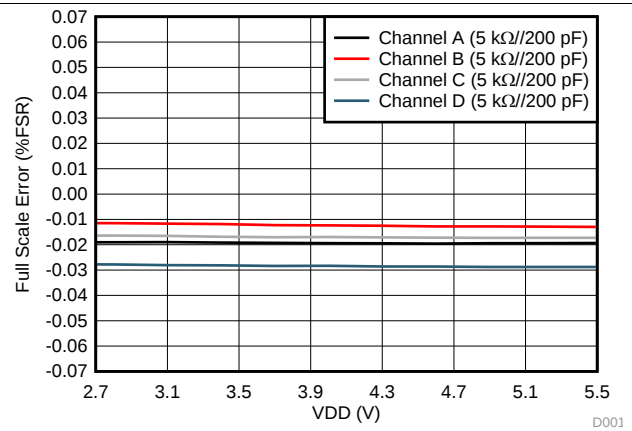


Figure 28. Full Scale Error vs Power Supply Voltage

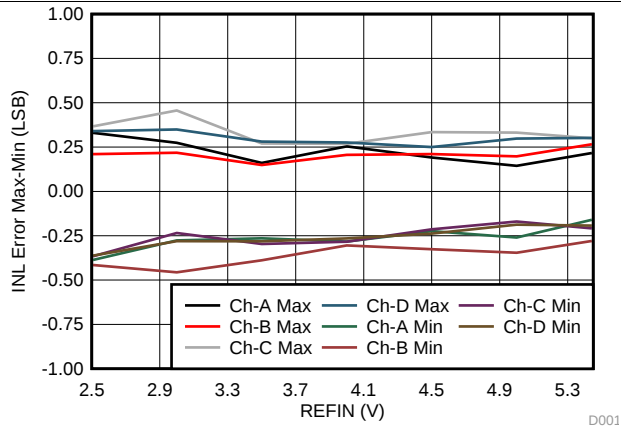


Figure 29. Linearity Error (Max-Min) vs Reference Voltage

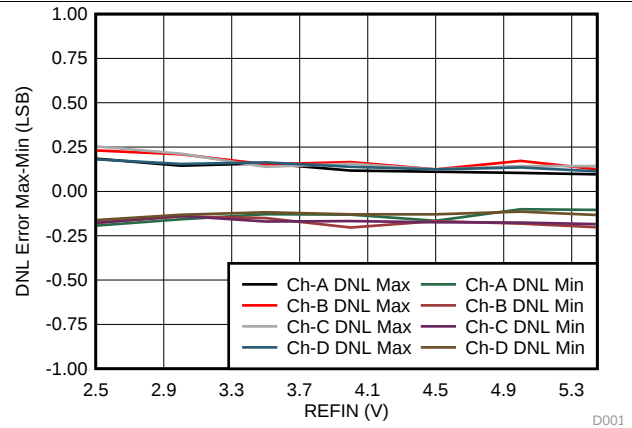


Figure 30. Differential Linearity Error (Max-Min) vs Reference Voltage

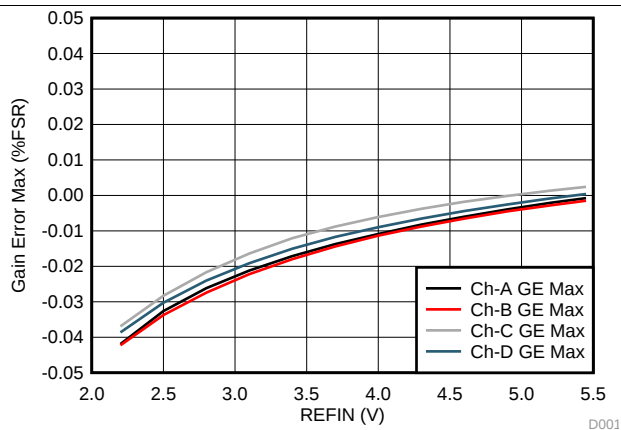


Figure 31. Gain Error (Max) vs Reference Voltage

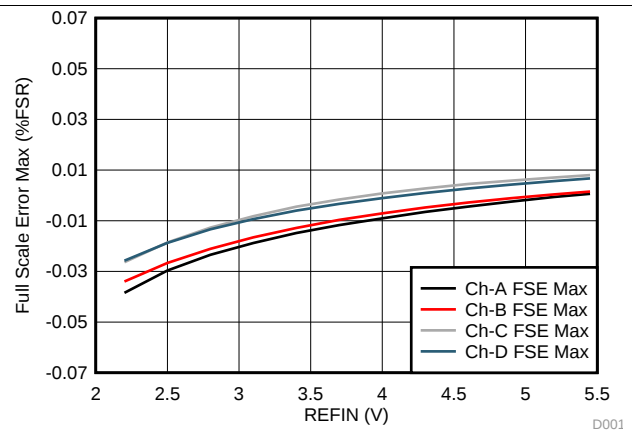


Figure 32. Full Scale Error (Max) vs Reference Voltage

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_{DD} = 5.5\text{ V}$, $\text{REFIN} = 5.45\text{ V}$, DAC outputs unloaded, All channels active, unless otherwise noted.

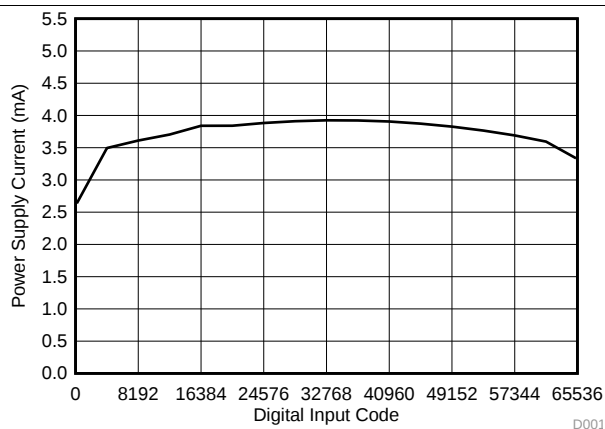
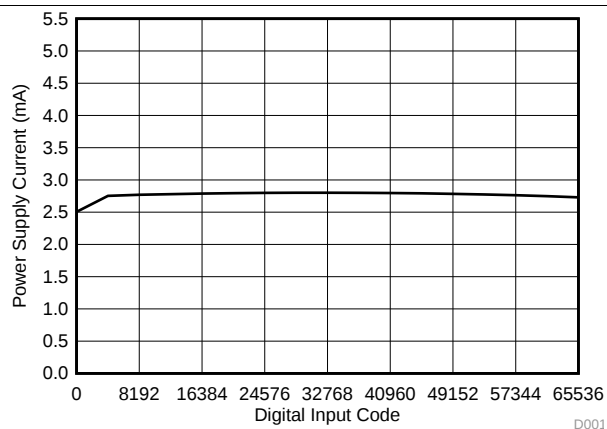
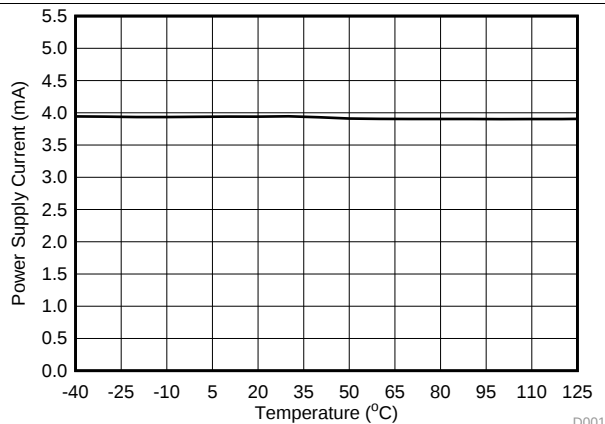


Figure 33. Power Supply Current vs Digital Input Code



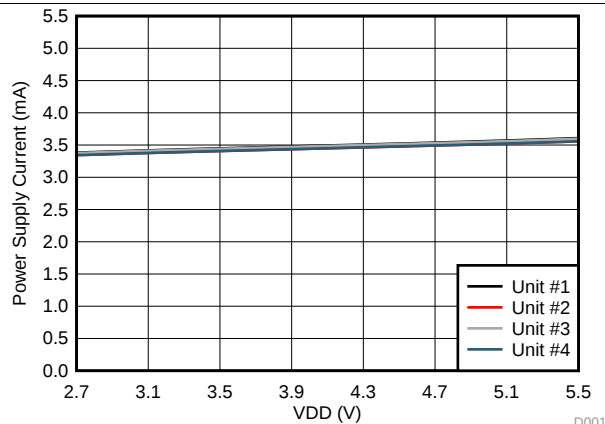
$V_{DD} = 2.7\text{ V}$, $\text{REFIN} = 2.5\text{ V}$

Figure 34. Power Supply Current vs Digital Input Code



DAC code = mid-scale code

Figure 35. Power Supply Current vs Temperature



$\text{REFIN} = 2.5\text{ V}$, DAC code = mid-scale code

Figure 36. Power Supply Current vs Power Supply Voltage

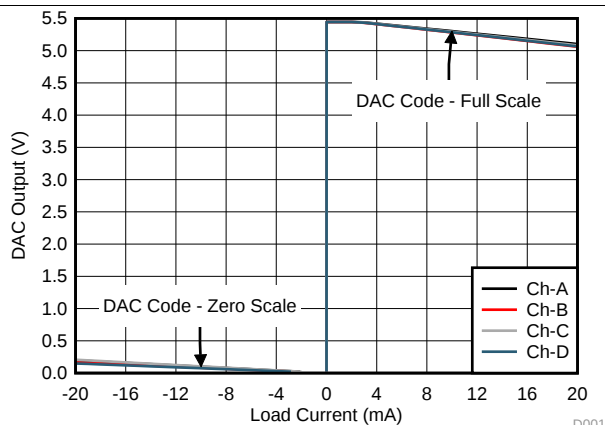
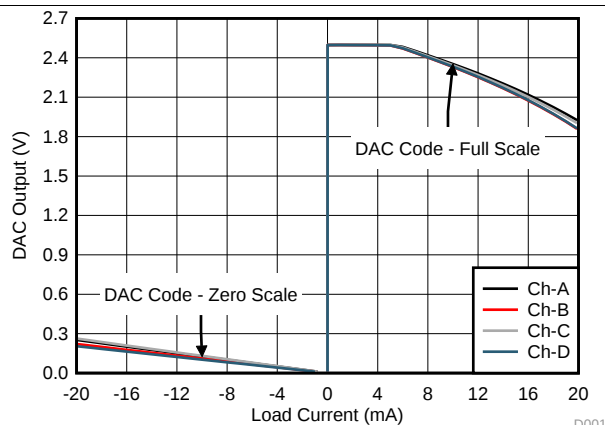


Figure 37. DAC Output Voltage vs Load Current



$V_{DD} = 2.7\text{ V}$, $\text{REFIN} = 2.5\text{ V}$

Figure 38. DAC Output Voltage vs Load Current

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_{DD} = 5.5\text{ V}$, $\text{REFIN} = 5.45\text{ V}$, DAC output load = $5\text{ k}\Omega\parallel 200\text{ pF}$, unless otherwise noted.

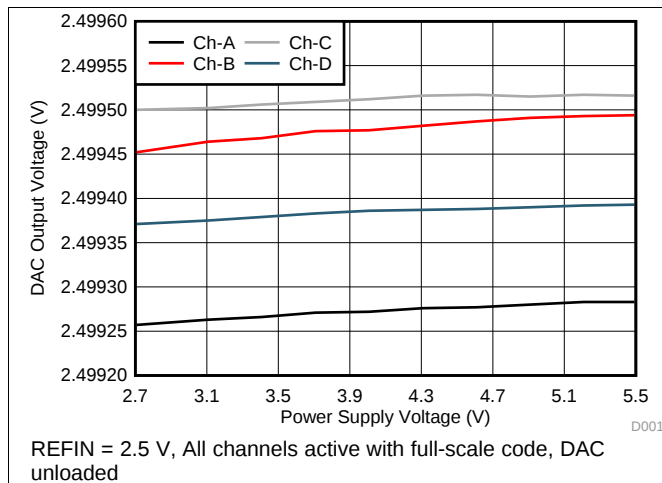


Figure 39. DAC Output Voltage vs Power Supply Voltage

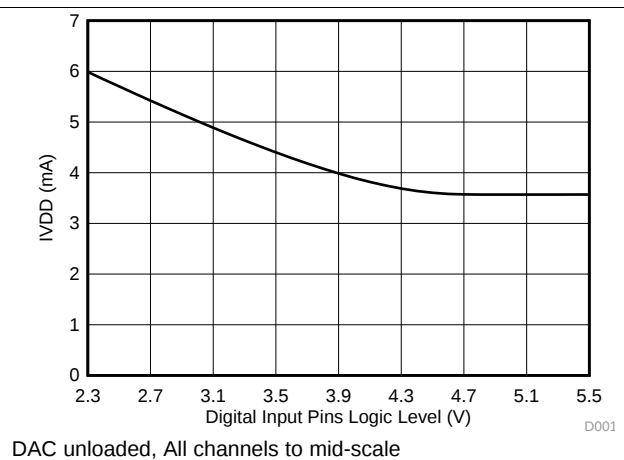


Figure 40. Power Supply Current vs Digital Input Pins Logic Level

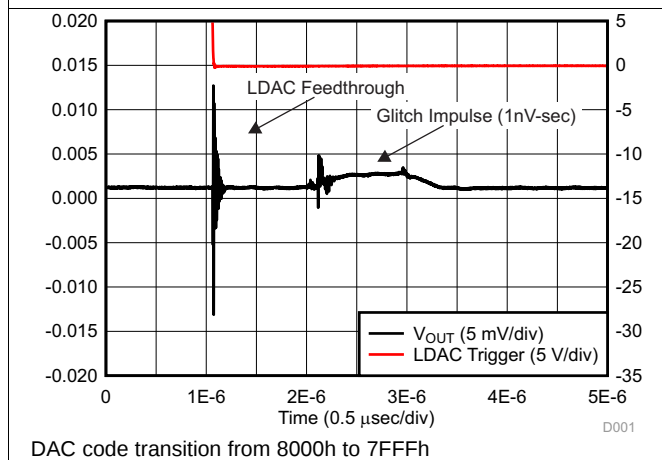


Figure 41. Glitch Impulse, Falling Edge, 1LSB Step

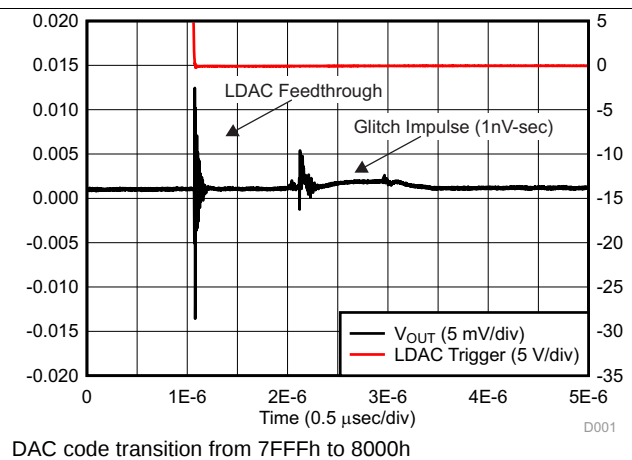


Figure 42. Glitch Impulse, Rising Edge, 1LSB Step

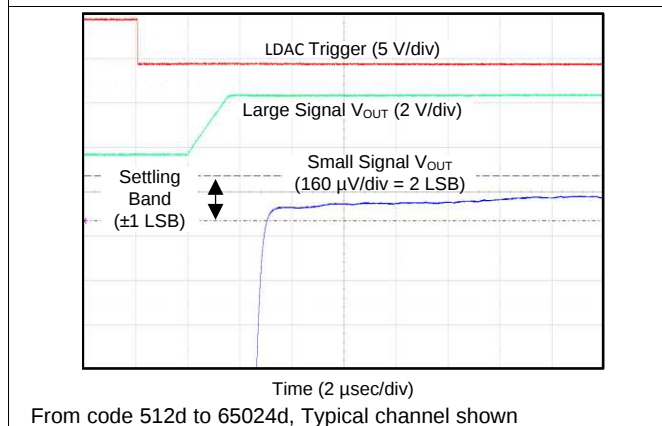


Figure 43. Full-Scale Settling Time, Rising Edge

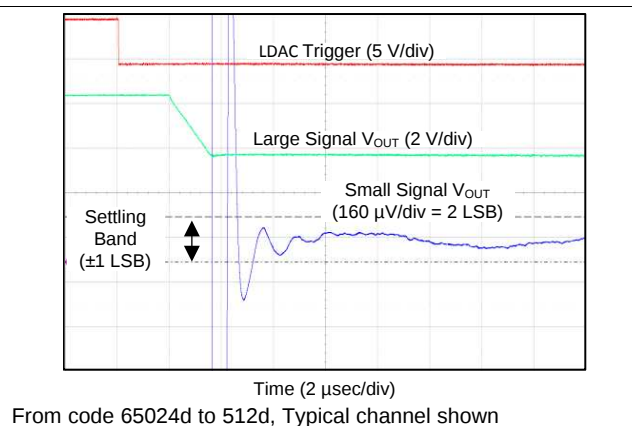
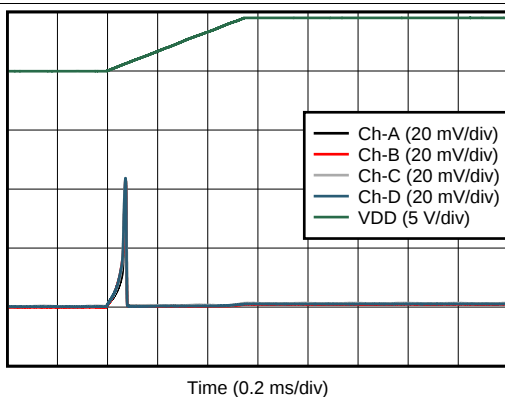


Figure 44. Full-Scale Settling Time, Falling Edge

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_{DD} = 5.5\text{ V}$, $\text{REFIN} = 5.45\text{ V}$, DAC output load = $5\text{ k}\Omega \parallel 200\text{ pF}$, unless otherwise noted.

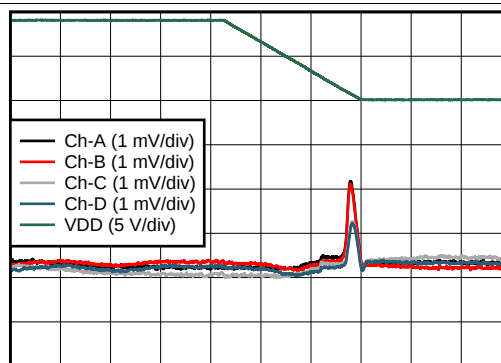


Time (0.2 ms/div)

DAC unloaded

D001

Figure 45. Power-On Glitch, Reset to Zero Scale

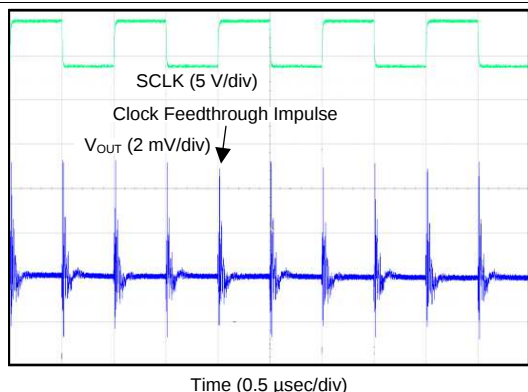


Time (2 ms/div)

DAC in power down mode ($1\text{ k}\Omega\text{-GND}$)

D001

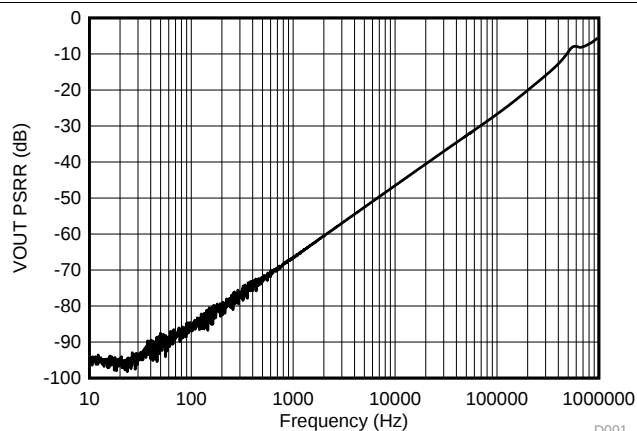
Figure 46. Power-Off Glitch, Reset to Zero Scale



Time (0.5 μsec/div)

DAC unloaded, DAC code mid-scale, Typical channel shown

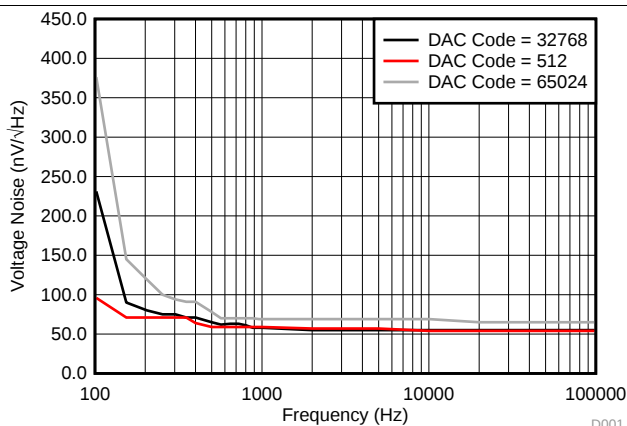
Figure 47. Clock Feedthrough, 1MHz Midscale



$V_{DD} = 5.0 + 1\text{ VPP}$ (Sinusoid), $\text{REFIN} = 2.5\text{ V}$, DAC code full-scale, Typical channel shown

D001

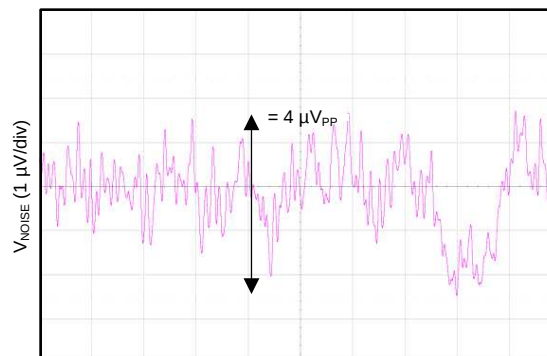
Figure 48. DAC Output AC PSRR vs VDD



DAC unloaded, Typical channel shown

D001

Figure 49. DAC Output Noise Density vs Frequency



DAC unloaded, DAC code mid-scale, Typical channel shown

Figure 50. DAC Output Noise, 0.1 Hz to 10 Hz

8 Detailed Description

8.1 Overview

The DAC80004, DAC70004, and DAC60004 are quad-channel, 16-bit, voltage-output DACs with internal reference buffers and output buffers. Each channel consists of an R-2R ladder configuration with the 4 MSBs segmented, followed by an operational amplifier, as shown in Figure 51. The DACx0004 devices have a constant impedance (30 kΩ typical), buffered reference input. The output of the reference buffers drives the R-2R ladders. With the production trim process these devices have excellent dc accuracy and ac performance.

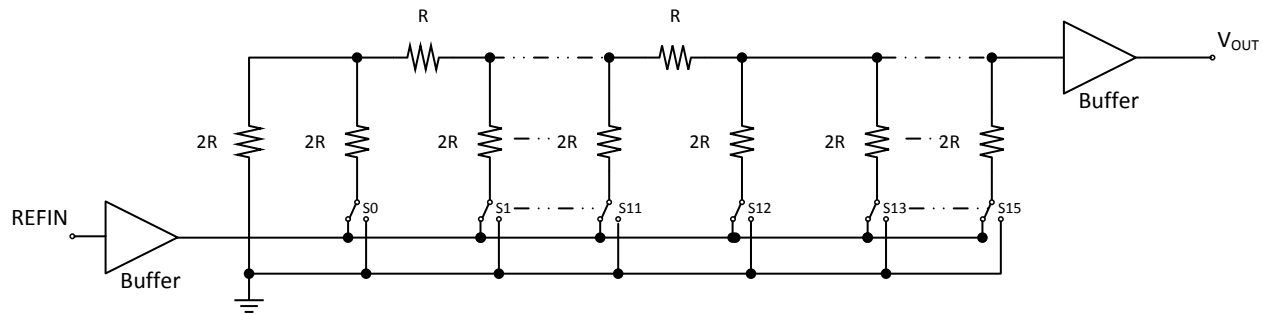


Figure 51. DACx0004 Architecture

The input coding to the DACx0004 is straight binary, so the ideal output voltage is given by Equation 1:

$$V_{OUT} = \left(\frac{D_{IN}}{2^N} \right) \times REF_{IN} \quad (1)$$

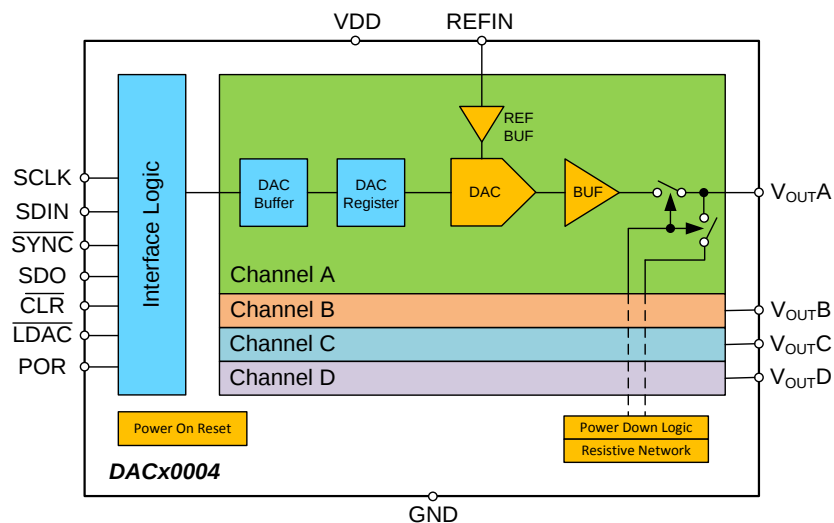
Where:

N = resolution in bits; either 16 (DAC80004), 14 (DAC70004) or 12 (DAC60004)

D_{IN} = decimal equivalent of the binary code that is loaded to the DAC register. D_{IN} ranges from 0 to 2^N – 1

REF_{IN} = DAC reference voltage

8.2 Functional Block Diagram



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8.3 Feature Description

8.3.1 Output Amplifier

The DACx0004 output buffer amplifier is capable of generating near rail-to-rail voltages on its output, giving a maximum output range of 0 V to REFIN. It is capable of driving a load of 5 k Ω in parallel with 2 nF to GND. The typical slew rate of this amplifier while driving no load is 1.5 V/ μ s, with a full-scale settling time of 8 μ s to 1 LSB of the final value as shown in [Figure 43](#) and [Figure 44](#). The current consumption of the amplifier (unloaded) is 1 mA/channel (typical). The DACx0004 output amplifier also implements a short circuit current limiting circuit. The default value of short circuit limit is 40 mA, however this can be reduced to 30 mA using dedicated bits (1 per channel) via SPI command 1010 (see [Table 2](#)).

8.3.2 Reference Buffer

The DACx0004 requires an external reference to operate. The reference input pin has the following input range:

2.2 V to ($V_{DD} - 0.2$) for $2.7\text{ V} \leq V_{DD} \leq 4.5\text{ V}$

2.2 V to V_{DD} for $4.5\text{ V} \leq V_{DD} \leq 5.5\text{ V}$

The DACx0004 contains a dedicated reference buffer for each DAC channel. The REFIN pin drives the input of these buffers. The integrated reference buffers offers constant impedance of 30 k Ω (typical) at the REFIN pin. This simplifies the external reference drive circuit for the device.

8.3.3 Power-On Reset

The DACx0004 contain a power-on-reset circuit that controls the output voltage during power up. The power-on reset is useful in applications where it is important to know the state of the output of each DAC while the device is in the process of powering up. At power up all DAC registers are filled with power-on reset code (see [Table 1](#)).

8.3.3.1 POR Pin Feature

The DAC power-on reset code for all of the channels depends on the state of the POR pin at power up (see [Pin Configuration and Functions](#)).

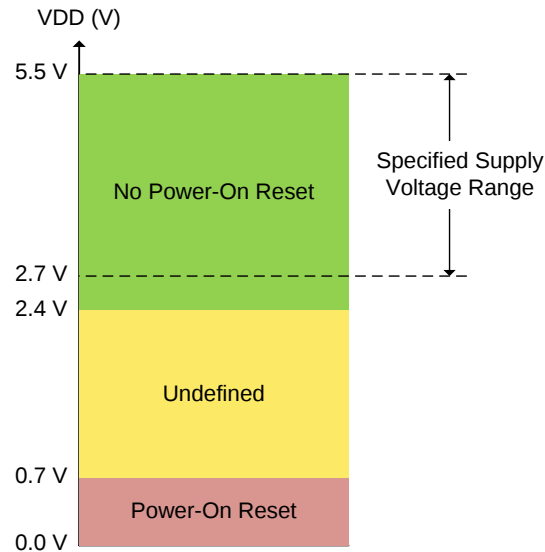
Each DAC channel remains that way until a valid load command is written to it. All device registers are reset at power up as shown in [Table 1](#).

Table 1. DACx0004 Power-On Reset Values

REGISTER NAME	DACx0004 - POWER-ON RESET VALUE
	TSSOP-/VSON-14
DAC latches (per channel)	If POR pin = '0' then Zero Scale else Mid scale
DAC buffers (per channel)	If POR pin= '0' then Zero Scale else Mid scale
Power down (per channel)	00 – Normal mode
Clear mode	00 – Clear to Zero
Ignore LDAC (per channel)	0000 – Do not ignore
Daisy chain	0 – Daisy chain disabled, DAC update at 32nd SCLK falling edge
Short circuit limit (per channel)	0000 – all DACs 40 mA

8.3.3.2 Internal Power-On Reset (IPOR) Levels

When the device powers up, an IPOR circuit sets the device in default mode as shown in [Table 1](#). The IPOR circuit requires specific V_{DD} levels, as indicated in [Figure 52](#), to ensure discharging of internal capacitors and to reset the device on power up. In order to ensure a power-on reset, V_{DD} must be below 0.7 V for at least 1 ms. When V_{DD} drops below 2.4 V but remains above 0.7 V (shown as the undefined region), the device may or may not reset under all specified temperature and power supply conditions. In this case, In this case a power-down reset is recommended. When V_{DD} remains above 2.4 V, a power-on reset does not occur.


Figure 52. Relevant Voltage Levels for IPOR Circuit

8.4 Device Functional Modes

8.4.1 Serial Interface

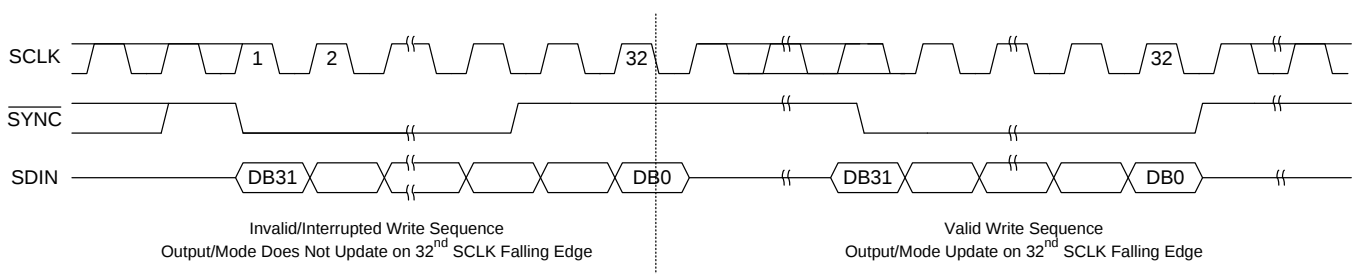
The DACx0004 devices have a 4-wire serial interface: $\overline{\text{SYNC}}$, SCLK, SDIN, and SDO (see [Pin Configuration and Functions](#)). The serial interface (3-wire and 4-wire) is compatible with SPI, QSPI, and Microwire interface standards, as well as most DSPs and it operates up to 50 MHz. See the Write Mode Stand-Alone Timing and Write Mode Daisy-Chain Timing diagrams (see [Figure 1](#) and [Figure 2](#)) for examples of typical write and read sequences. The input shift register is 32 bits wide.

8.4.1.1 Stand-Alone Mode

The serial clock SCLK can be a continuous or a gated clock. The first falling edge of $\overline{\text{SYNC}}$ starts the operation cycle. When $\overline{\text{SYNC}}$ is high, the SCLK and SDIN signals are blocked and the SDO pin (TSSOP-14 and VSON-14 packages) is in a Hi-Z state. The device internal registers are updated from the shift register on the 32nd falling edge of SCLK.

8.4.1.1.1 $\overline{\text{SYNC}}$ Interrupt – Stand-Alone Mode

For stand-alone operation, the $\overline{\text{SYNC}}$ line stays low for at least 32 falling edges of SCLK and the addressed DAC register updates on the 32nd SCLK falling edge. However, if $\overline{\text{SYNC}}$ is brought high before the 32nd SCLK falling edge, it acts as an interrupt to the write sequence; the shift register resets and the write sequence is discarded. Neither an update of the data buffer contents, DAC register contents, nor a change in the operating mode occurs (as shown in [Figure 53](#)).


Figure 53. $\overline{\text{SYNC}}$ Interrupt – Stand Alone Operation

Device Functional Modes (continued)

8.4.1.1.2 Read-Back Mode

The READ command is used to start read-back operation. However, before read-back operation can be initiated, the SDO pin must be enabled by setting the DSDO bit to '1'; this bit is disabled by default. Read-back operation is then started by executing a READ command (R/W bit = '1', see [Table 3](#)). Bits C3 to C0 select the register to be read. The remaining data in the command are don't care bits. During the next SPI operation, the data appearing on the SDO output are from the previously addressed register. For a read of a single register, a NOP (No Operation) command (1110) can be used to clock out the data from the selected register on SDO. Multiple registers can be read if multiple READ commands are issued (see [Figure 54](#)).

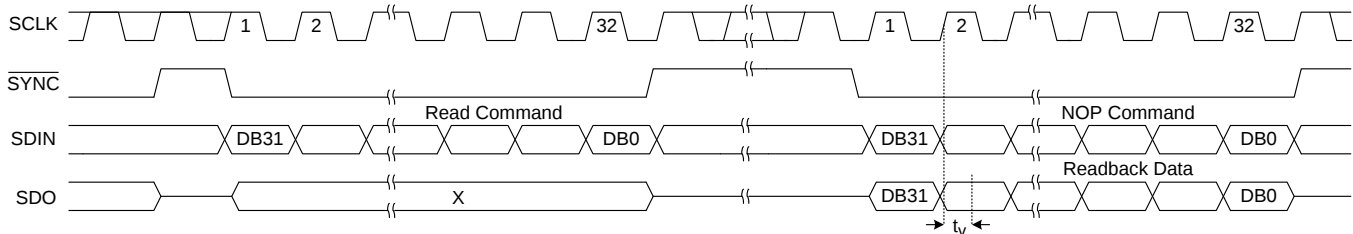


Figure 54. Read-Back Operation

8.4.1.2 Daisy-Chain Mode

For systems that contain more than one device, the SDO pin can be used to daisy-chain multiple devices together (see [Figure 55](#)). Daisy-chain operation can be useful in system diagnostics and in reducing the number of serial interface lines. The daisy-chain feature can be enabled by writing a logic '1' to the DSDO bit (see [Table 3](#)); the SDO pin is set to HIZ when the DSDO bit is set to 0.

The first falling edge of $\overline{\text{SYNC}}$ starts the operating cycle. SCLK is continuously applied to the SPI shift register when $\overline{\text{SYNC}}$ is low. If more than 32 clock pulses are applied, the data ripples out of the shift register and appear on the SDO line. The data bits are clocked out on the rising edge of SCLK and are valid on the falling edge. By connecting the SDO pin of the first device to the SDI input of the next device in the chain, a multiple-device interface is constructed (see [Figure 2](#)). Each device in the system requires 32 clock pulses. Therefore, the total number of clock cycles must equal $32 \times N$, where N is the total number of DACx0004s in the chain. When the serial transfer to all devices is complete, $\overline{\text{SYNC}}$ is taken high. This action latches the data from the SPI shift registers to the device internal registers for each device in the daisy-chain and prevents any further data from being clocked in. The serial clock can be a continuous or a gated clock. Note that a continuous SCLK source can only be used if $\overline{\text{SYNC}}$ is held low for the correct number of clock cycles. For gated clock mode, a burst clock containing the exact number of clock cycles must be used and $\overline{\text{SYNC}}$ must be taken high after the final clock in order to latch the data.

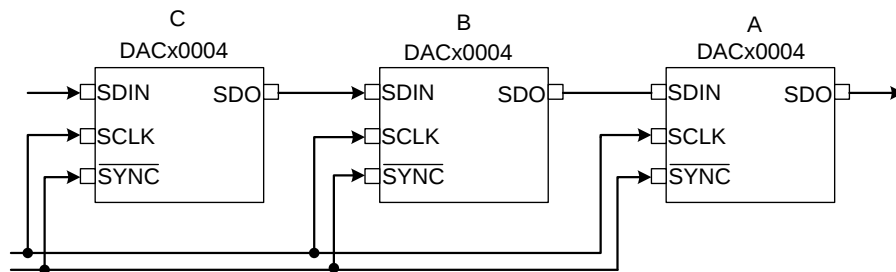


Figure 55. DACx0004 in Daisy Chain Mode

8.4.1.2.1 $\overline{\text{SYNC}}$ Interrupt – Daisy-Chain Mode

For daisy-chain operation, the $\overline{\text{SYNC}}$ line stays low for at least $32 \times N$ SCLK cycles, where N is the number of DACx0004s in the daisy chain. If $\overline{\text{SYNC}}$ is brought high before a multiple 32 SCLKs, it acts as an interrupt to the write sequence; the shift register resets and the write sequence is discarded. Neither an update of the data buffer contents, DAC register contents, nor a change in the operating mode occurs (see [Figure 56](#)).

Device Functional Modes (continued)

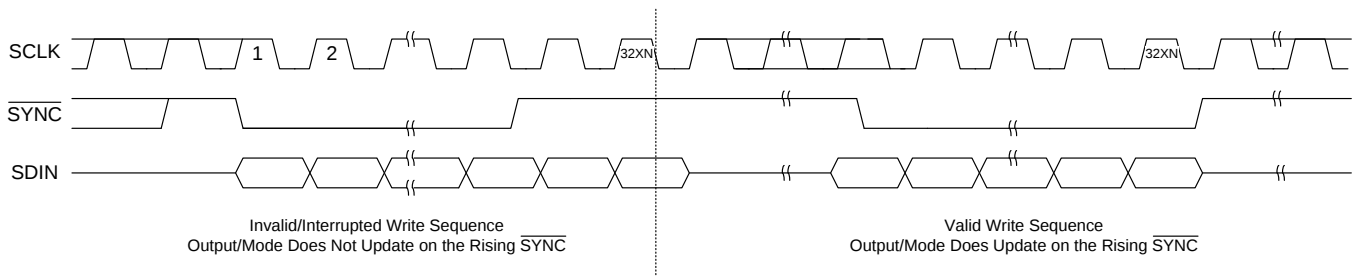


Figure 56. SYNC Interrupt – Daisy-Chain Operation

8.4.2 SPI Shift Register

The SPI shift register is 32 bits wide, as shown in Table 2. The shift register command mapping is shown in Table 3. The DACx0004 accepts DAC code in straight binary format. Note that, the DAC data is left aligned from MSB (D19) to LSB (D4 - 16 bits, D6 - 14 bits, D8 - 12 bits).

Table 2. DACx0004 SPI Shift Register Format

D31	D30	D29	D28	D27-D24	D23-D20	D19-D04	D03-D00
Don't Cares			R/W	Command Bits	Channel Address Bits	16/14/12-Bit DAC Data left aligned/Power Down Bits/Device Ready bit	Mode Bits

Table 3. DAC Commands

D31 - D28		D27 - D24				D23 - D20	D19 - D16	D15 - D12	D11 - D08			D07 - D04	D03 - D00				Commands	
X	$\overline{W}/R$	0	0	0	0	Channel Address	DAC Data	DAC Data	DAC Data			DAC Data	X				Write to buffer n	
X	$\overline{W}$	0	0	0	1	Channel Address	X	X	X			X	X				Update DAC n	
X	$\overline{W}$	0	0	1	0	Channel Address	DAC Data	DAC Data	DAC Data			DAC Data	X				Write to buffer n and update all DACs (Software LDAC)	
X	$\overline{W}$	0	0	1	1	Channel Address	DAC Data	DAC Data	DAC Data			DAC Data	X				Write to buffer and update DAC n	
X	$\overline{W}/R$	0	1	0	0	X	X	X	X	PD1	PD0		Ch-D	Ch-C	Ch-B	Ch-A	Power up/down DAC n	
X	$\overline{W}/R$	0	1	0	1	X	X	X	X			X	X	X	CM1	CM0	Clear mode register	
X	$\overline{W}/R$	0	1	1	0	X	X	X	X			X	Ch-D	Ch-C	Ch-B	Ch-A	LDAC register	
X	$\overline{W}$	0	1	1	1	X	X	X	X			X	X				Software reset	
X	$\overline{W}/R$	1	0	0	0	X	X	X	X			X	X		DSD0	X	Disable SDO register	
X	X	1	0	0	1	X	X	X	X			X	X				Reserved	
X	$\overline{W}/R$	1	0	1	0	X	X	X	X			X	Ch-D	Ch-C	Ch-B	Ch-A	Short circuit limit register	
X	$\overline{W}$	1	0	1	1	X	X	X	X			X	X				Software clear	
X	X	1	1	0	0	X	X	X	X			X	X				Reserved	
X	R	1	1	0	1	X	X	X	X			X	X	X				Status register
X	$\overline{W}$	1	1	1	0	X	X	X	X			X	X				No operation (NOP)	
X	X	1	1	1	1	X	X	X	X			X	X				Reserved	

Table 4. Channel Address Bits

CHANNEL ADDRESS BITS				DESCRIPTION
D23	D22	D21	D20	
0	0	0	0	Select channel A
0	0	0	1	Select channel B
0	0	1	0	Select channel C
0	0	1	1	Select channel D
1	1	1	1	Select all channel

8.4.3 DAC Power-Down Modes

The DACx0004 use four modes of operation. These modes are accessed by setting command bits D28 – D24 and power-down register bits D09 and D08. The command bits must be set to 0100 (see Table 3). Once the command bits are set correctly, the four different power-down modes are software programmable by setting bits D09 and D08 in the shift register. Table 5 shows how to control the operating mode with data bits PD1 (D09), PD0 (D08).

Table 5. Power-Down Bits

POWER DOWN BITS		DESCRIPTION
D09	D08	
0	0	Normal operation/power up selected channel(s) (Default)
0	1	Power down selected channel(s) 1 kΩ-GND
1	0	Power down selected channel(s) 100 kΩ-GND
1	1	Power down selected channel(s) Hi-Z

It is possible to write to the DAC register/buffer of the DAC channel that is powered down. When the DAC channel is then powered up, it powers up to this new value.

The advantage of the available power-down modes is that the output impedance of the device is known while it is in power-down mode. As described in Table 5, there are three different power-down options. V_{OUTX} can be connected internally to GND through a 1 kΩ resistor, a 100 kΩ resistor, or open-circuited (Hi-Z). The DAC power-down circuitry is shown in Figure 57.

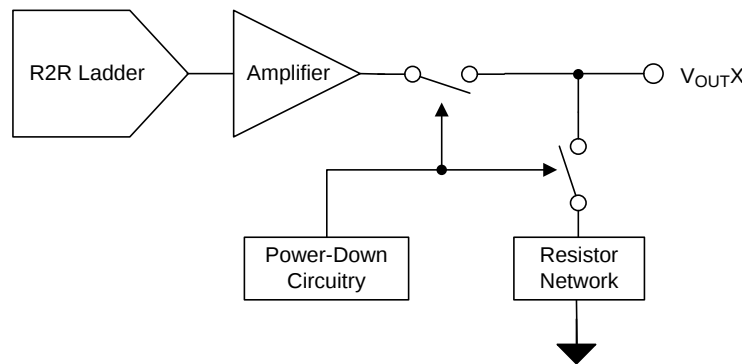


Figure 57. DACx0004 Power Down

8.4.4 CLR Pin Functionality and Software CLEAR Mode

The $\overline{\text{CLR}}$ pin is an asynchronous input pin to the DAC. When activated, this falling edge sensitive pin clears the DAC buffers and the DAC latches to zero, mid, full or user programmed code depending on the clear mode register (see Table 6). The default setting for clear operation is clear to 0 V. The device exits clear mode on the 32nd falling edge of the next write to the device. If the $\overline{\text{CLR}}$ pin receives a falling edge signal during a write sequence in normal operation, the clear mode is activated and changes the input and DAC registers immediately. Additionally, all DAC registers can also be cleared via SPI command 1011. Note that the clear mode bits determine the clear code for all the DACs upon clear operation.

8.4.4.1 DAC Clear Mode Registers

The DACx0004 implement four different clear modes. These modes are accessed by setting command bits D28 – D24 and clear mode register bits D01 and D00. The command bits must be set to 0101 (see Table 3). Based on the value of clear mode register (see Table 6), all of the DAC and the buffers are cleared to zero, mid, or full-scale code, when the $\overline{\text{CLR}}$ pin sees a falling edge or after a software clear command is issued.

The user defined clear scale can be set by writing 16-/14-/12- data to 1001 to bits D28 – D24.

Table 6. Clear Mode Bits

CLEAR MODE BITS		DESCRIPTION
D01	D00	
0	0	All DACs clear to zero scale (default)
0	1	All DACs clear to mid scale
1	0	All DACs clear to full scale

8.4.5 $\overline{\text{LDAC}}$ Pin Functionality

The DACx0004 devices offer both a software and hardware simultaneous update and control function. The DAC double-buffered architecture has been designed so that new data can be entered for each DAC without disturbing the analog outputs. Data updates can be performed either in synchronous or in asynchronous mode.

In asynchronous mode, the $\overline{\text{LDAC}}$ pin is used as an active low signal for simultaneous DAC updates. Multiple single-channel writes can be done in order to set different channel buffers to desired values and then pulse the $\overline{\text{LDAC}}$ pin low to simultaneously update the DAC output registers. Data buffers of all channels must be loaded with desired data before an $\overline{\text{LDAC}}$ low pulse. After a $\overline{\text{LDAC}}$ low pulse, all DACs are simultaneously updated with the last contents of the corresponding data buffers. If the content of a data buffer is not changed, the corresponding DAC output remains unchanged after the $\overline{\text{LDAC}}$ pin is pulsed low.

In synchronous mode, data are updated with the falling edge of the 32nd SCLK cycle, which follows a falling edge of SYNC. For such synchronous updates, the $\overline{\text{LDAC}}$ pin is not required, and it must be connected to GND permanently or asserted and held low before sending commands to the device.

8.4.5.1 Software $\overline{\text{LDAC}}$ Mode Registers

Alternatively, all DAC outputs can be updated simultaneously using the built-in software function of $\overline{\text{LDAC}}$. The $\overline{\text{LDAC}}$ register offers additional flexibility and control by allowing the selection of which DAC channel(s) should be updated simultaneously when the $\overline{\text{LDAC}}$ pin is being brought low. The $\overline{\text{LDAC}}$ register is loaded with a 4-bit word (D03 and D00) using command bits D28 – D24 (see Table 3). The default value for each bit, and therefore for each DAC channel, is zero. If the $\overline{\text{LDAC}}$ register bit is set to 1, it overrides the $\overline{\text{LDAC}}$ pin (the $\overline{\text{LDAC}}$ pin is internally tied low for that particular DAC channel), and this DAC channel updates synchronously after the falling edge of the 32nd SCLK cycle. However, if the $\overline{\text{LDAC}}$ register bit is set to 0, the DAC channel is controlled by the $\overline{\text{LDAC}}$ pin.

See Table 7 for more information.

Table 7. $\overline{\text{LDAC}}$ Register

$\overline{\text{LDAC}}$ REGISTER BITS (D03 – D00)	DAC UPDATE
0	Determined by $\overline{\text{LDAC}}$ pin (Default)
1	DAC channel ignores $\overline{\text{LDAC}}$ pin, DAC updates on 32nd falling edge of SCLK, DAC channels see $\overline{\text{LDAC}}$ as 0

8.4.6 Software Reset Mode

The DACx0004 implements a software reset feature. The software reset function uses command bits D28 – D24 (see Table 3). Table 1 shows the reset values for different registers.

8.4.7 Output Short Circuit Limit Register

The DACx0004 output amplifier has a default short circuit limit of 40 mA. However, this limit can be reduced to 30 mA by using command 1010 on bits D28 – D24 and selecting channel(s) (D03 – D00). Please note that DACx0004 has a dedicated bit per channel, this allows the user to set different short circuit limit for different DAC output channels.

Table 8. Short Circuit Limit Register

SHORT CIRCUIT LIMIT REGISTER BITS (D03 – D00)	DAC SHORT CIRCUIT LIMIT
0	DAC output short circuit limit = 40 mA (Default)
1	DAC output short circuit limit = 30 mA

8.4.8 Status Register

The DACx0004 implements a read-only status register (see [Table 3](#)). This register can be read by using command 1101 on bits D28 – D24, followed by a NOP command.

Logic '1' on bit D04 indicates that the device is ready to be used. This feature is useful to check if the device is ready to accept commands after power up.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.2 Typical Application - Digitally Controlled Asymmetric Bipolar Output

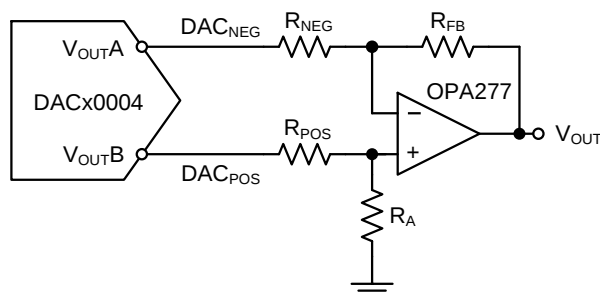


Figure 58. Asymmetric Bipolar Output Block Diagram

9.2.1 Design Requirements

This design requires two channels of the DACx0004 to generate a bipolar output. The design is very flexible and allows for many different configurations. Typically, one channel is used to finely control the output, while the other is used to offset the output. The direction of the offset depends on which channel is used as an offset. DAC_{POS} provides a positive offset and DAC_{NEG} has a negative offset.

9.2.2 Detailed Design Procedure

The output of each DAC can be modified via the digital interface and the gain of each output can be modified independently by changing the external resistors. In order for the gain of each offset to be independent, [Equation 2](#) must be true.

$$R_A = \left(\frac{1}{R_{FB}} + \frac{1}{R_{NEG}} - \frac{1}{R_{POS}} \right)^{-1} \quad (2)$$

The output voltage range, V_{OUT} , is adjusted according to [Equation 3](#). Keep in mind that [Equation 3](#) is only true when [Equation 2](#) is true.

$$V_{OUT} = DAC_{POS} \times \frac{R_{FB}}{R_{POS}} - DAC_{NEG} \times \frac{R_{FB}}{R_{NEG}} \quad (3)$$

Each DAC outputs a voltage from 0 to REFIN. As an example, if DAC_{POS} gain is 1, DAC_{NEG} gain is 2 and $R_{FB} = 2 \text{ k}\Omega$, then $R_{POS} = 2 \text{ k}\Omega$, $R_{NEG} = 1 \text{ k}\Omega$ and $R_A = 1 \text{ k}\Omega$. With the correct digital implementation it gives the output an effective output range of $\pm 15 \text{ V}$, with discrete 16-bit steps.

Typical Application - Digitally Controlled Asymmetric Bipolar Output (continued)

9.2.3 Application Curve

Figure 59 displays two different modes of operation. Mode 1 gains the output of DAC_{Neg} by a factor of 2 and maintains DAC_{POS} at unity gain. Mode 2 reverses the gains of each stage to invert the system. These are just two examples of the types of outputs that can be achieved using this configuration.

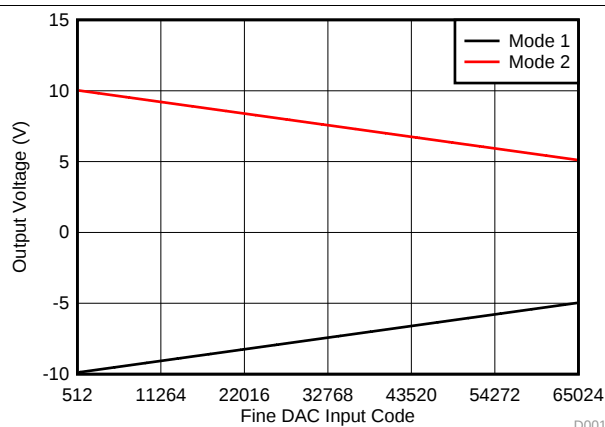


Figure 59. Output Voltage vs Fine DAC Input Code

10 Power Supply Recommendations

The DACx0004 can operate within the specified supply voltage range of 2.7 V to 5.5 V. The power applied to VDD should be well-regulated and have low-noise. Switching power supplies and DC-DC converters often have high frequency glitches or spikes riding on the output voltage. In addition, digital components can create similar high frequency spikes. This noise can easily couple into the DAC output voltage through various paths between the power connections and analog output. A 1 μ F to 10 μ F capacitor and 0.1 μ F bypass capacitor is recommended in order to further minimize noise from the power supply. The current consumption on the VDD pin, the short-circuit current limit, and the load current for the device are listed in the [Electrical Characteristics](#). The power supply must meet the aforementioned current requirements.

11 Layout

11.1 Layout Guidelines

A precision analog component requires careful layout, adequate bypassing, and clean, well-regulated power supplies. As a general rule it is important to keep digital traces as far away from analog traces when possible.

The DACx0004 is often used in close proximity with digital logic, microcontrollers, microprocessors, and digital signal processors. The more digital logic present in the design and the higher the switching speed, the more difficult it is to keep digital noise from appearing at the output.

Due to the single ground pin of the DACx0004, all return currents, including digital and analog return currents for the DAC, must flow through a single point. Ideally, GND must be connected directly to an analog ground plane. This plane must be separate from the ground connection for the digital components until they were connected at the power-entry point of the system.

As with the GND connection, VDD should be connected to a 5 V power-supply plane or trace that is separate from the connection for digital logic until they are connected at the power-entry point. It is recommended to have an additional 1 μ F to 10 μ F capacitor and 0.1 μ F bypass capacitor. In some situations, additional bypassing may be required, such as a 100 μ F electrolytic capacitor or even a Pi filter made up of inductors and capacitors—all designed to essentially low-pass filter the 5 V supply, removing the high-frequency noise. In general it is always a good idea to maintain the digital signals away from analog signals.

11.2 Layout Example

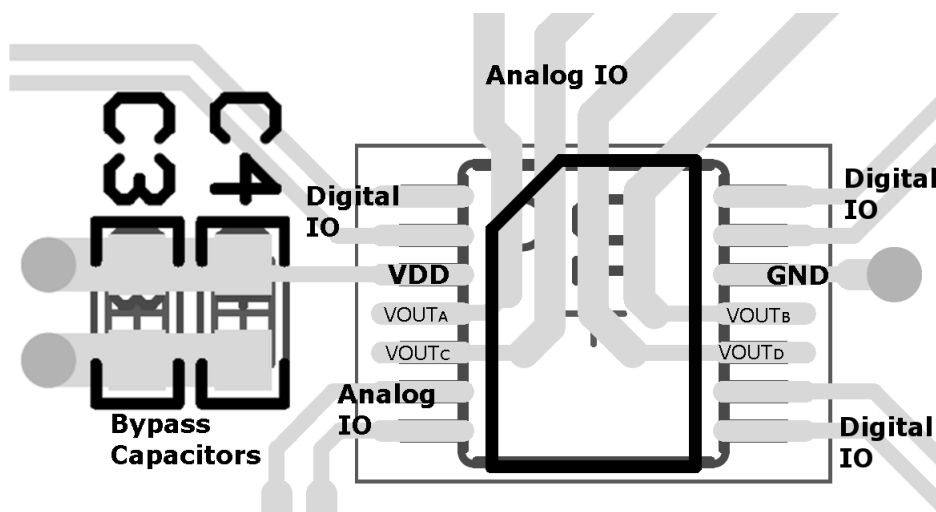


Figure 60. Layout Diagram

12 デバイスおよびドキュメントのサポート

12.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の隅にある「通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

12.2 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびサンプル注文またはご購入へのクイック・アクセスが含まれます。

表 9. 関連リンク

製品	プロダクト・フォルダ	サンプルとご購入	技術資料	ツールとソフトウェア	サポートとコミュニティ
DAC60004	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
DAC70004	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
DAC80004	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

12.3 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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設計サポート *TIの設計サポート* 役に立つE2Eフォーラムや、設計サポート・ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。

12.4 商標

E2E is a trademark of Texas Instruments.

SPI, QSPI are trademarks of Motorola.

All other trademarks are the property of their respective owners.

12.5 静電気放電に関する注意事項



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12.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

DAC80004IPWのデバイス・マーキング情報: DA80004およびXDC84は、いずれもDAC80004IPW発注デバイスの有効なデバイス・マーキングです。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DAC60004IDMDR	Active	Production	VSON (DMD) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC60004IDMDR.B	Active	Production	VSON (DMD) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC60004IDMDT	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC60004IDMDT.B	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC60004IPW	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC60004IPW.B	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC60004IPWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC60004IPWR.B	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA60004
DAC70004IDMDR	Active	Production	VSON (DMD) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC70004IDMDR.B	Active	Production	VSON (DMD) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC70004IDMDT	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC70004IDMDT.B	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC70004IPW	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC70004IPW.B	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC70004IPWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC70004IPWR.B	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA70004
DAC80004IDMDR	Active	Production	VSON (DMD) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IDMDR.B	Active	Production	VSON (DMD) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IDMDT	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IDMDT.B	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IDMDTG4	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IDMDTG4.B	Active	Production	VSON (DMD) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IPW	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IPW.B	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IPWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IPWR.B	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IPWRG4	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004
DAC80004IPWRG4.B	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	DA80004

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

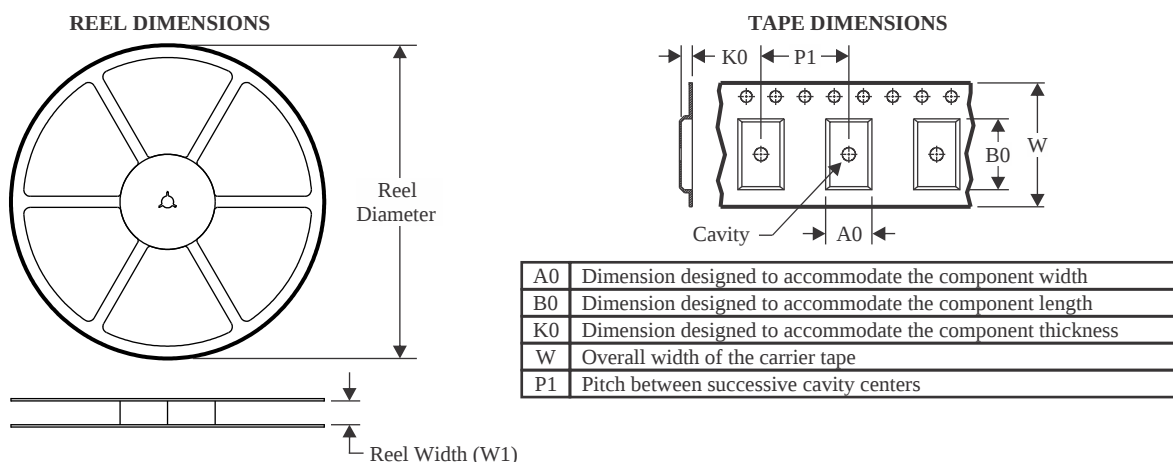
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

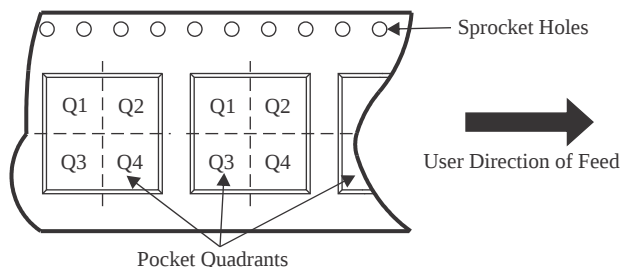
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TAPE AND REEL INFORMATION



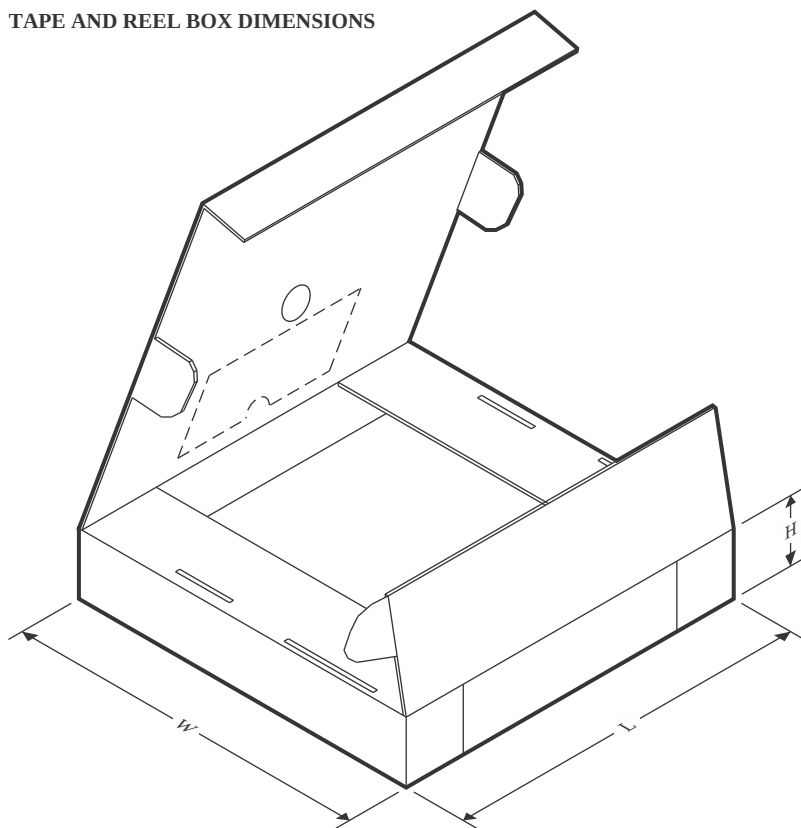
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DAC60004IDMDR	VSON	DMD	14	3000	330.0	12.4	3.3	4.3	1.1	8.0	12.0	Q1
DAC60004IDMDT	VSON	DMD	14	250	180.0	12.4	3.3	4.3	1.1	8.0	12.0	Q1
DAC60004IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
DAC70004IDMDR	VSON	DMD	14	3000	330.0	12.4	3.3	4.3	1.1	8.0	12.0	Q1
DAC70004IDMDT	VSON	DMD	14	250	180.0	12.4	3.3	4.3	1.1	8.0	12.0	Q1
DAC70004IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
DAC80004IDMDR	VSON	DMD	14	3000	330.0	12.4	3.3	4.3	1.1	8.0	12.0	Q1
DAC80004IDMDT	VSON	DMD	14	250	180.0	12.4	3.3	4.3	1.1	8.0	12.0	Q1
DAC80004IDMDTG4	VSON	DMD	14	250	180.0	12.4	3.3	4.3	1.1	8.0	12.0	Q1
DAC80004IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
DAC80004IPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

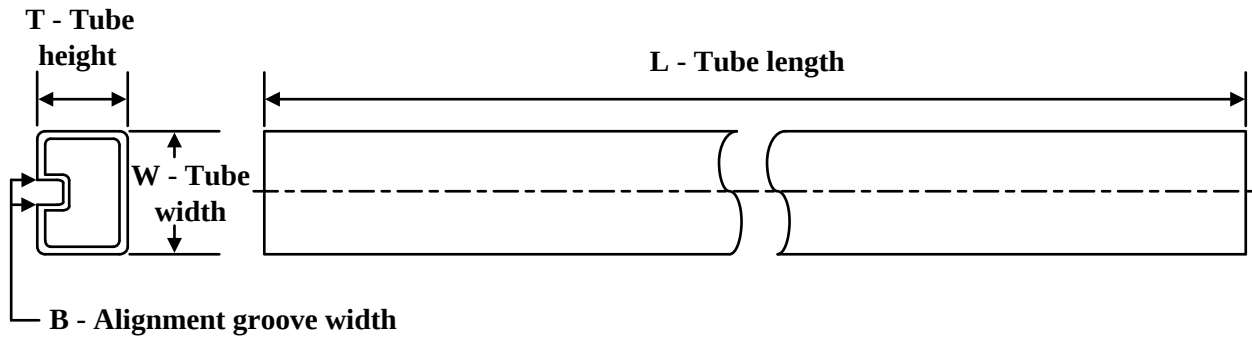
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

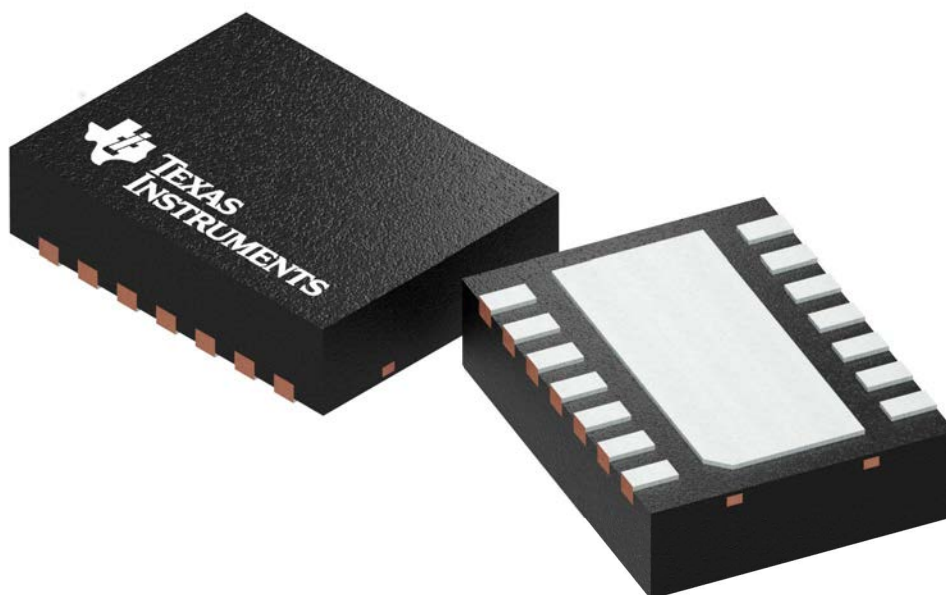
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DAC60004IDMDR	VSON	DMD	14	3000	367.0	367.0	38.0
DAC60004IDMDT	VSON	DMD	14	250	213.0	191.0	35.0
DAC60004IPWR	TSSOP	PW	14	2000	353.0	353.0	32.0
DAC70004IDMDR	VSON	DMD	14	3000	367.0	367.0	38.0
DAC70004IDMDT	VSON	DMD	14	250	213.0	191.0	35.0
DAC70004IPWR	TSSOP	PW	14	2000	353.0	353.0	32.0
DAC80004IDMDR	VSON	DMD	14	3000	367.0	367.0	38.0
DAC80004IDMDT	VSON	DMD	14	250	213.0	191.0	35.0
DAC80004IDMDTG4	VSON	DMD	14	250	213.0	191.0	35.0
DAC80004IPWR	TSSOP	PW	14	2000	353.0	353.0	32.0
DAC80004IPWRG4	TSSOP	PW	14	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DAC60004IPW	PW	TSSOP	14	90	530	10.2	3600	3.5
DAC60004IPW.B	PW	TSSOP	14	90	530	10.2	3600	3.5
DAC70004IPW	PW	TSSOP	14	90	530	10.2	3600	3.5
DAC70004IPW.B	PW	TSSOP	14	90	530	10.2	3600	3.5
DAC80004IPW	PW	TSSOP	14	90	530	10.2	3600	3.5
DAC80004IPW.B	PW	TSSOP	14	90	530	10.2	3600	3.5



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



VSON - 1 mm max height

Diagram illustrating the dimensions and a specific area of a rectangular component:

- The total width is 3.1.
- The distance from the left edge to the right edge of the shaded area is 2.9.
- The total height is 4.1.
- The distance from the bottom edge to the bottom edge of the shaded area is 3.9.
- The shaded area is labeled "PIN 1 INDEX AREA".
- Points A and B are marked at the top corners of the component.

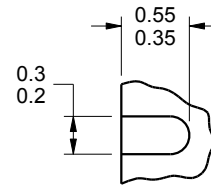
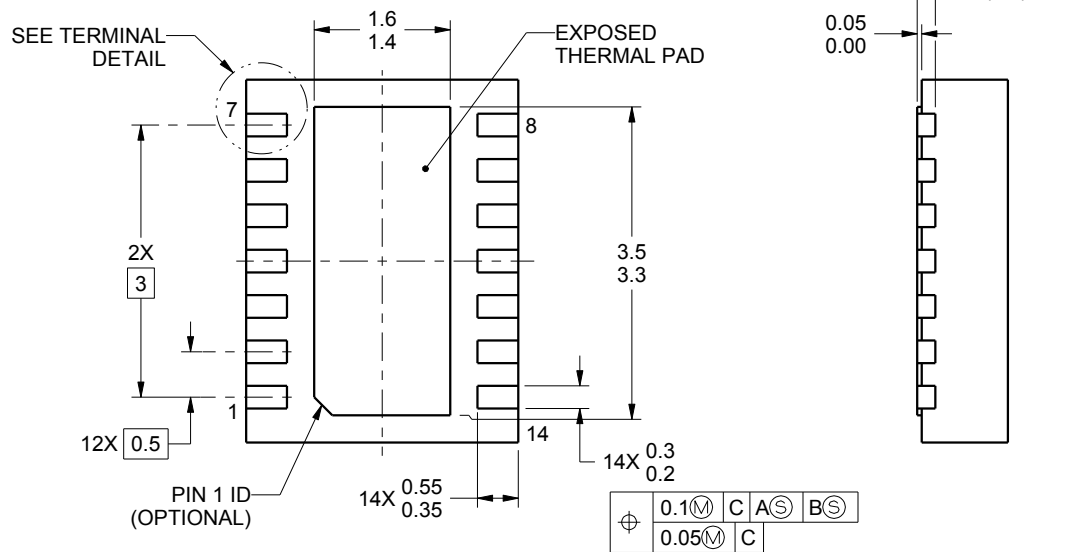


Diagram illustrating the seating plane and head position. The diagram shows a side view of a person sitting at a table. The head is positioned above the table surface, with a vertical distance labeled "1 MAX". The table surface is labeled "SEATING PLANE". A small box labeled "C" is positioned above the table surface, and a larger box labeled "0.08 C" is positioned below the table surface.



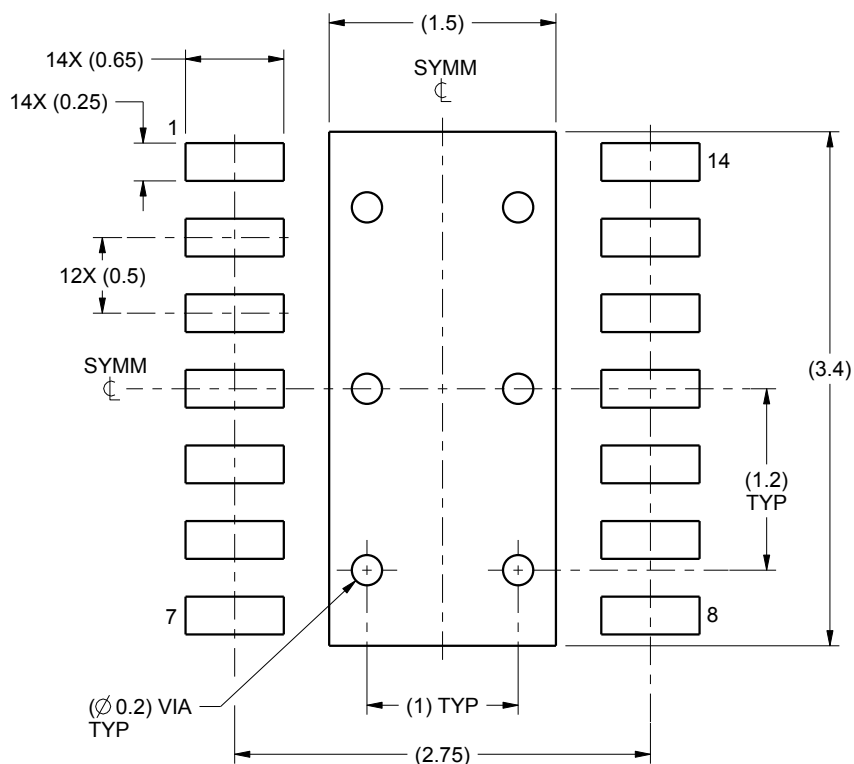
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

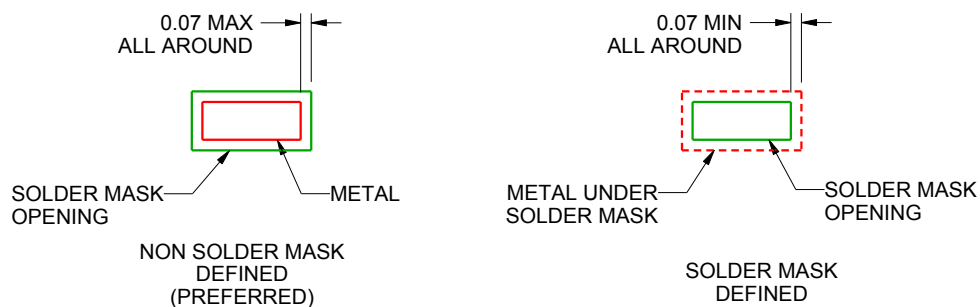
DMD0014A

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

4221688/A 09/2014

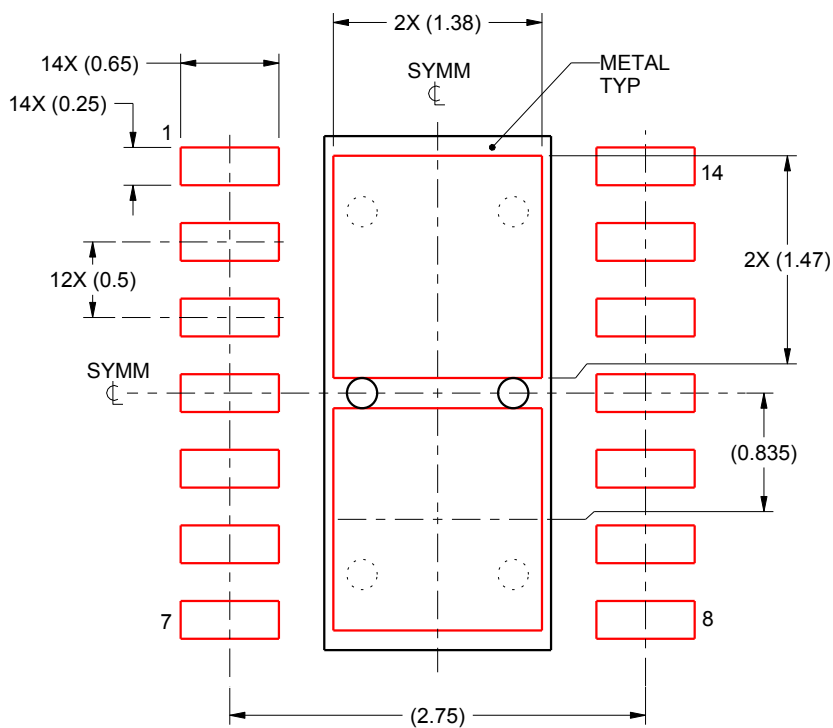
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

DMD0014A

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



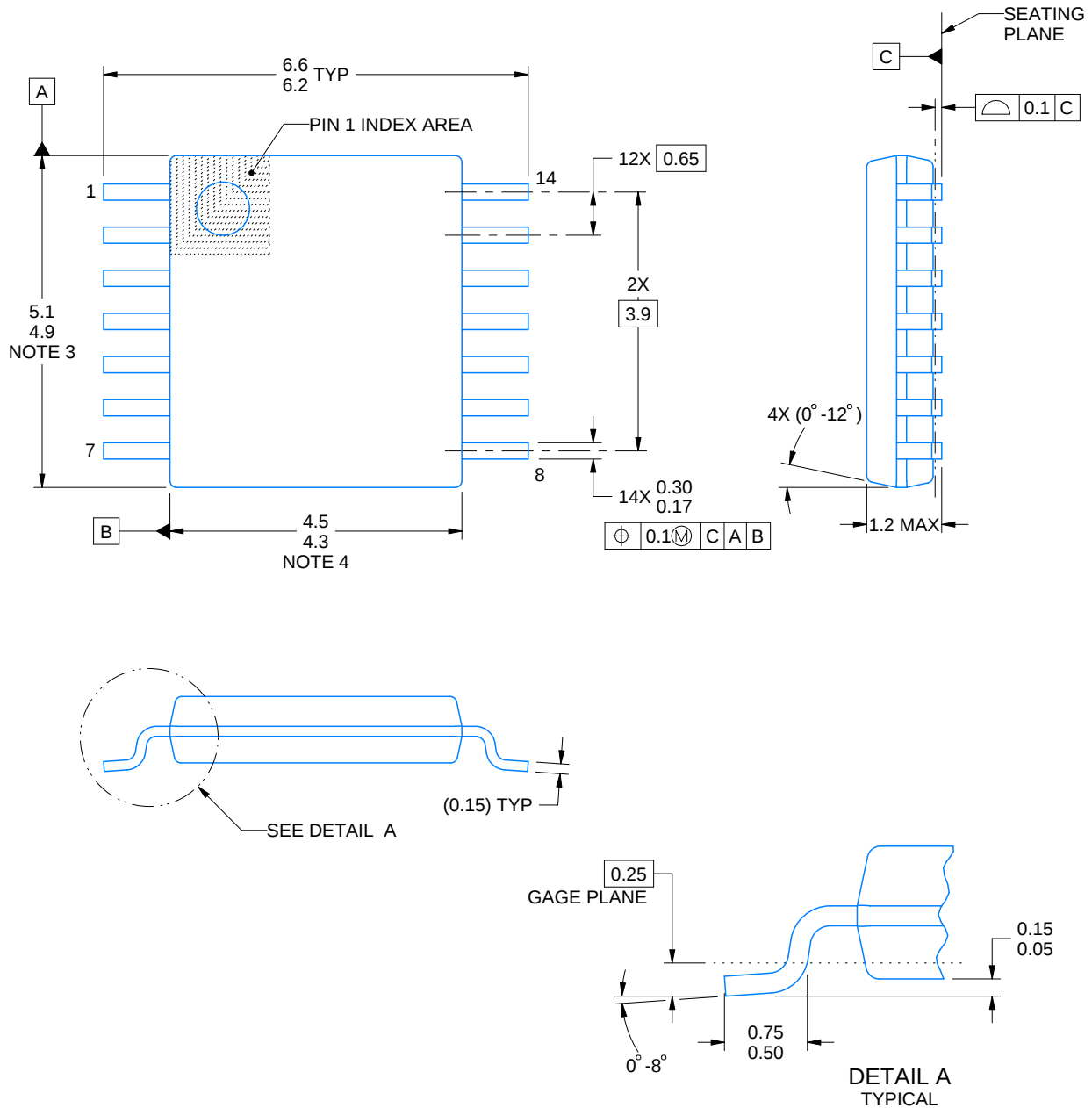
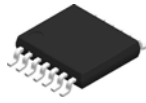
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
80% PRINTED SOLDER COVERAGE BY AREA
SCALE:20X

4221688/A 09/2014

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



4220202/B 12/2023

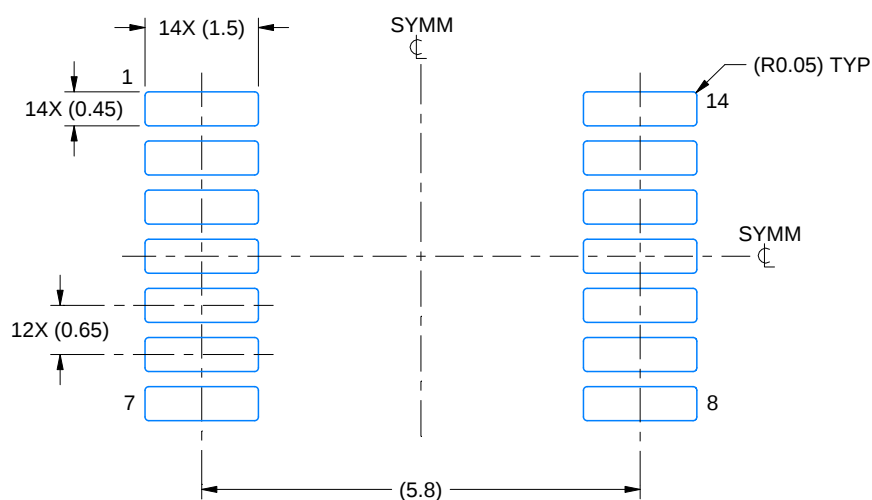
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

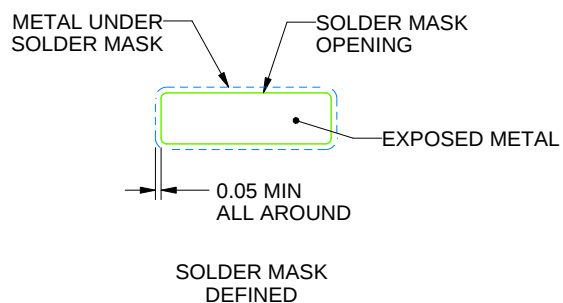
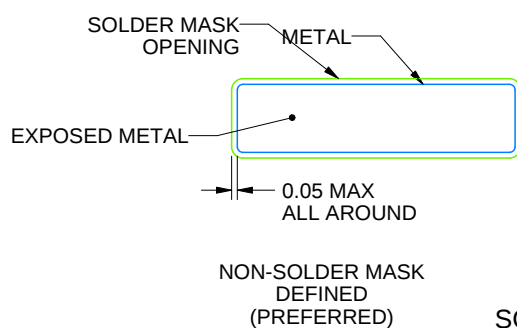
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

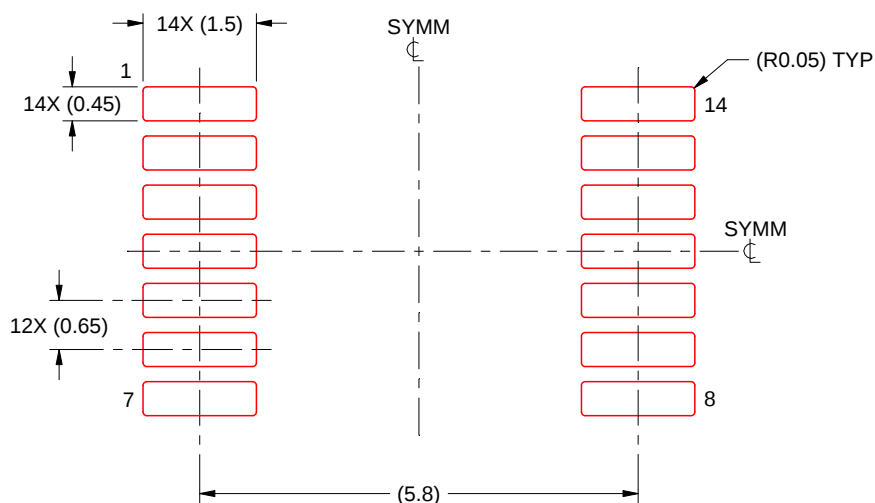
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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最終更新日：2025 年 10 月